

# 350 kV Photoelectron Gun with Inverted-Insulator Geometry

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COOL'15 Workshop, Jefferson Lab, September 28 – October 2, 2015

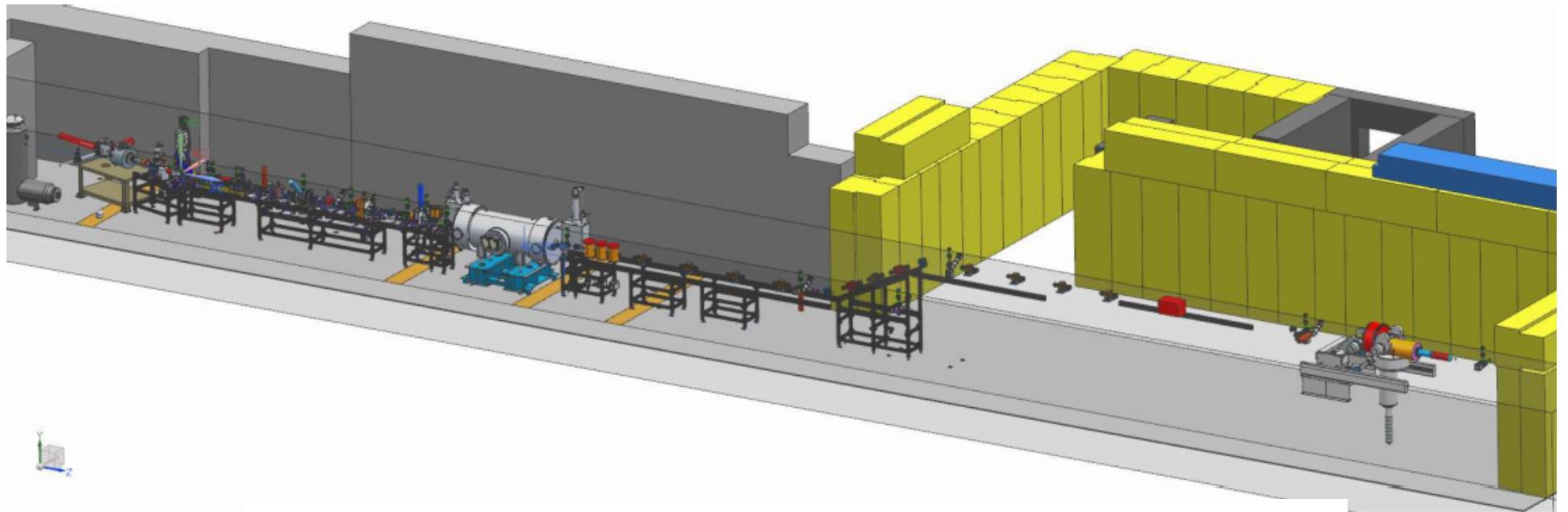
# A NEW PHOTOGUN FOR NEW INITIATIVES

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- Compact 10 MeV accelerator to commission new hardware destined for CEBAF
  - Polarized target for Hall B - HDIce
  - New SRF capture section for injector
  - Test bed to improve beam quality for demanding parity-violation experiments
- Load-locked gun for JLab's FEL/ERL for DarkLight and other experiments
  - DC high voltage gun, but with CsK<sub>2</sub>Sb photocathode
- Electron Ion Collider (MEIC, eRHIC, LHeC)
  - High average current polarized beams and very high current un-polarized beams for cooling proton beams
  - Magnetized beam



350kV inverted gun + chopper + buncher + “traditional” JLab  $\frac{1}{4}$  cryomodule



10 MeV beam to commission HDIce

# ERL Circulator Cooler Concept

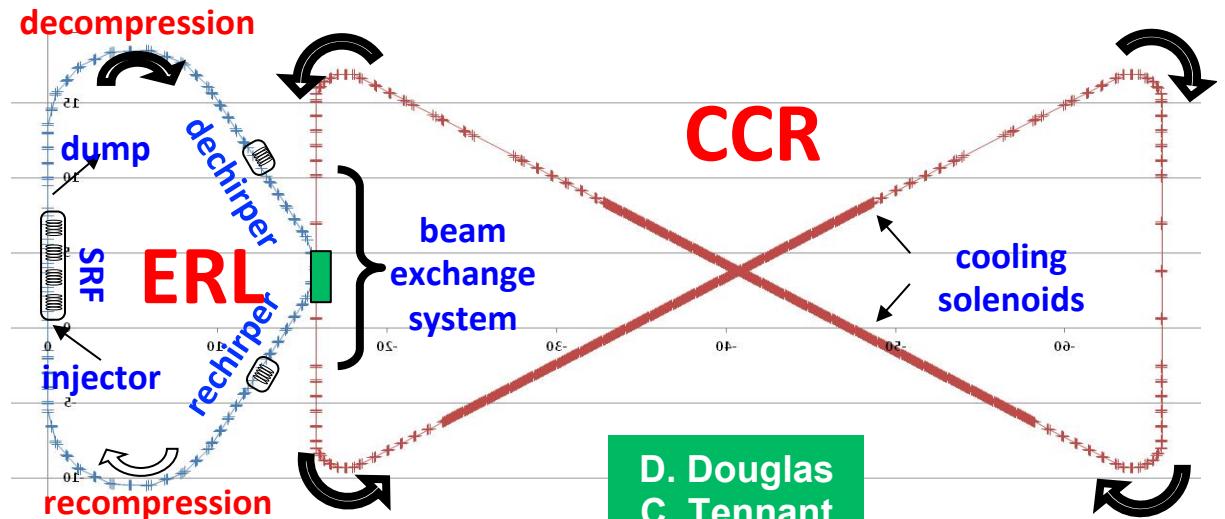
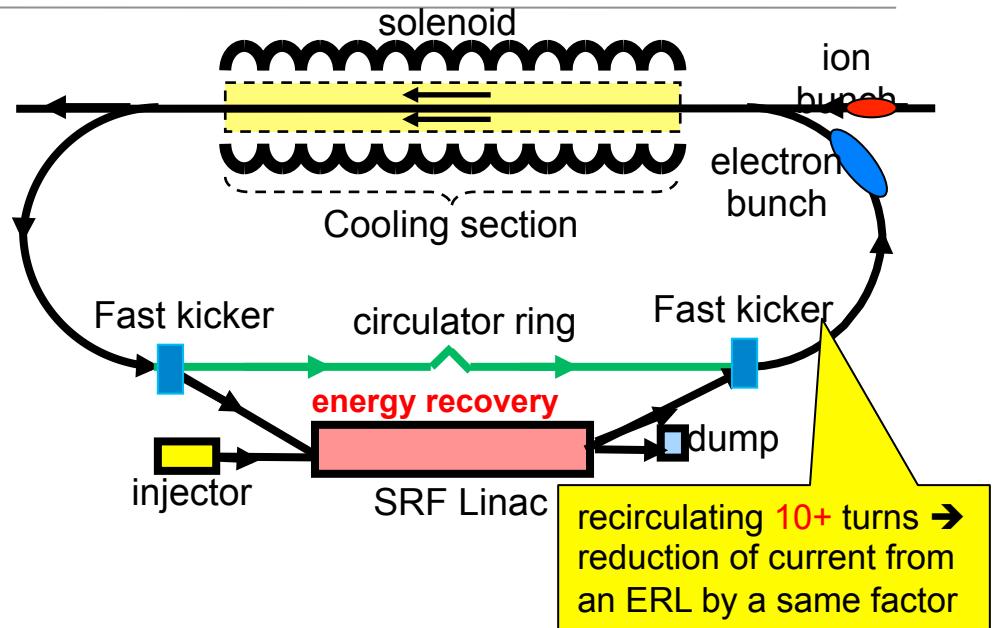
## Design Choices

- Energy Recovery Linac (ERL)
- Compact circulator ring to meet design challenges
- Large RF power, up to 81 MW
- Very high electron beam current: 1.5 A

## Required technologies

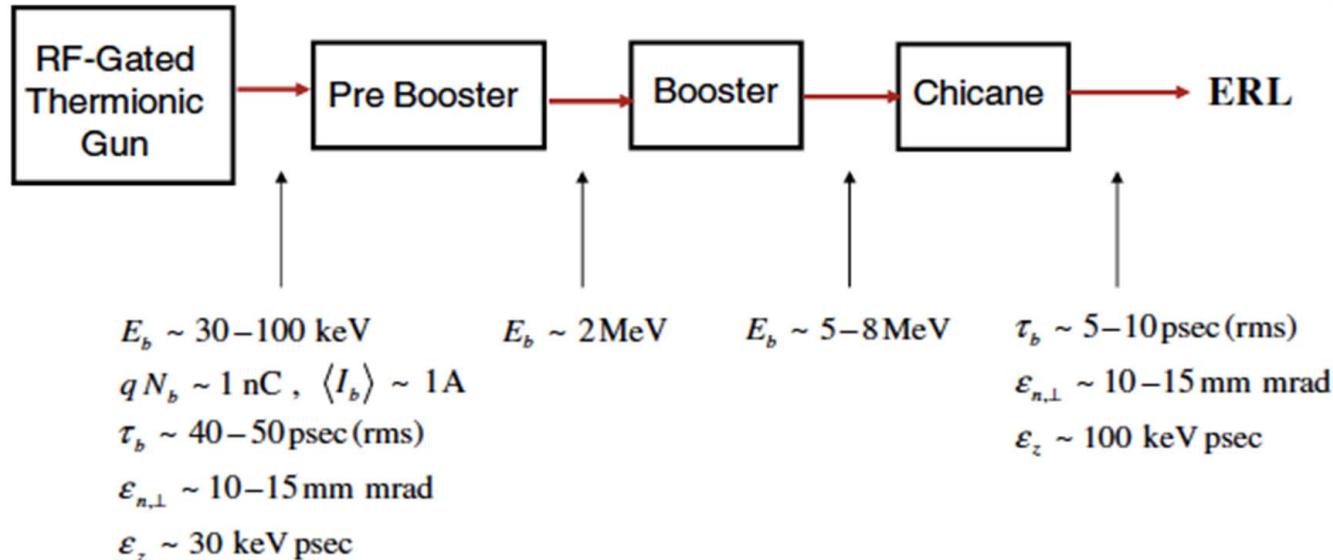
- High current ERL (55 MeV, 15 to 150 mA)
- Magnetized beam
- High bunch charge (2 nC)
- Ultra fast kicker

Proposed by S. Derbenev



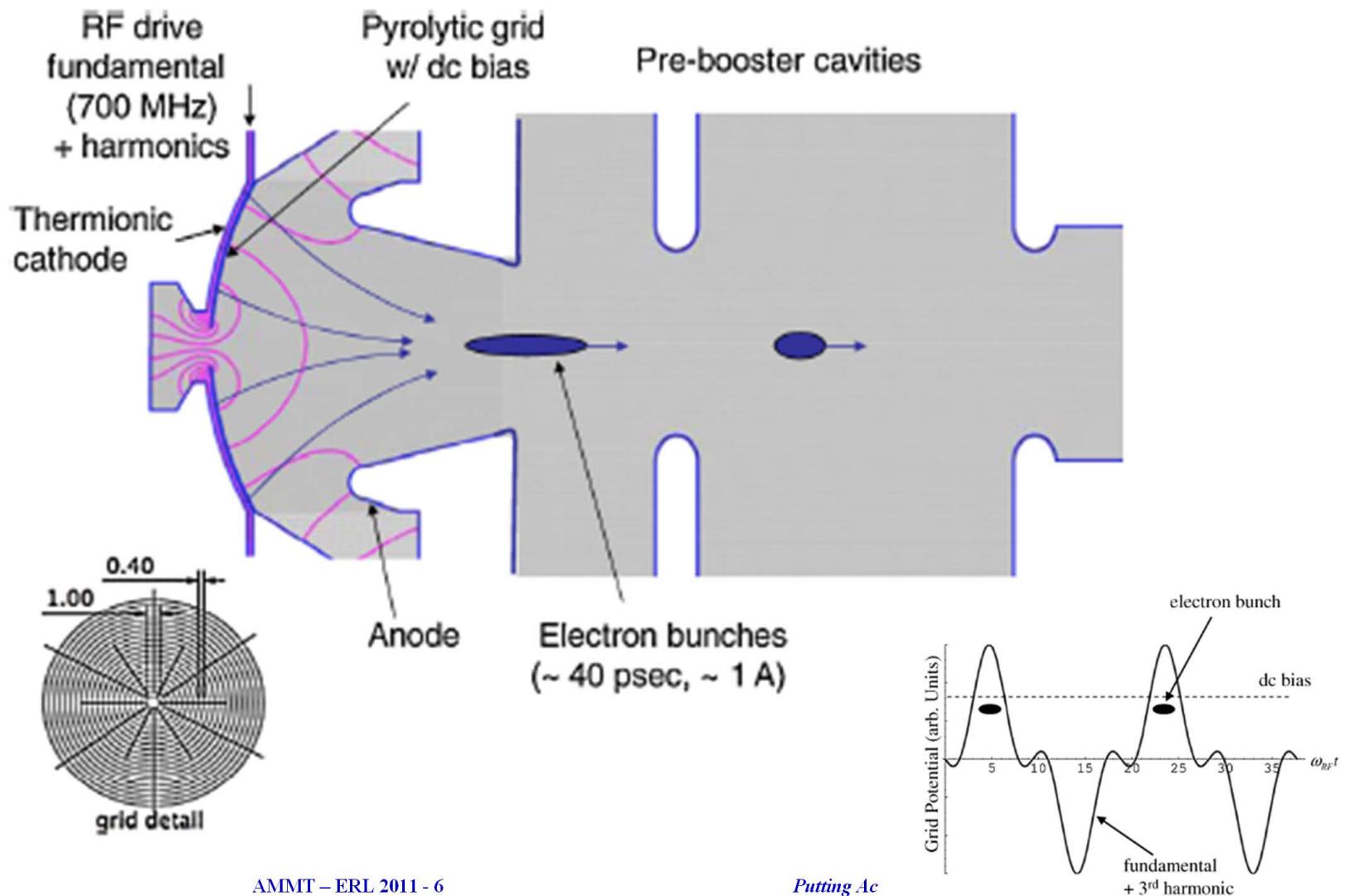
# AES gridded thermionic cathode in RF gun

## NRL Injector Concept



Alan Todd, AES, presented at ERL 11 Workshop, Tsukuba, Japan

# AES gridded thermionic cathode in RF gun



AMMT – ERL 2011 - 6

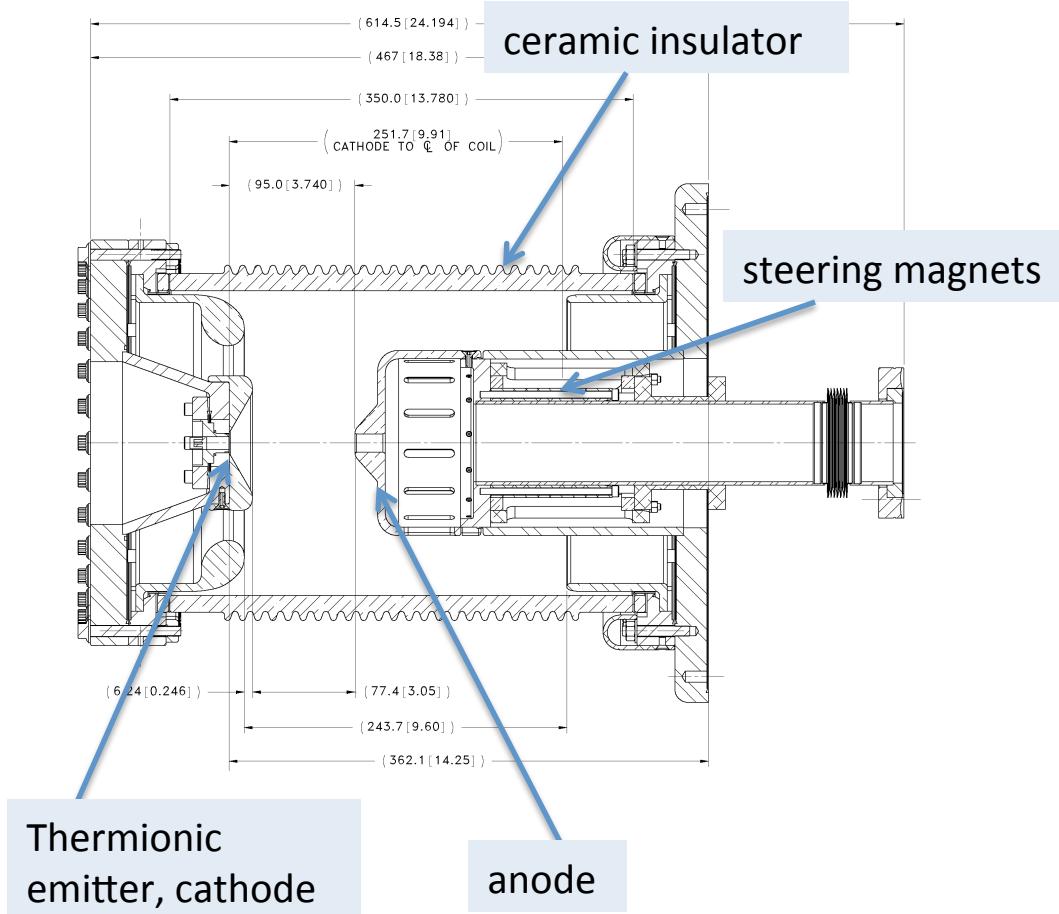
Putting Ac

Alan Todd, AES, presented at ERL 11 Workshop, Tsukuba, Japan

Matt Poelker, Jefferson Lab

Slide 6

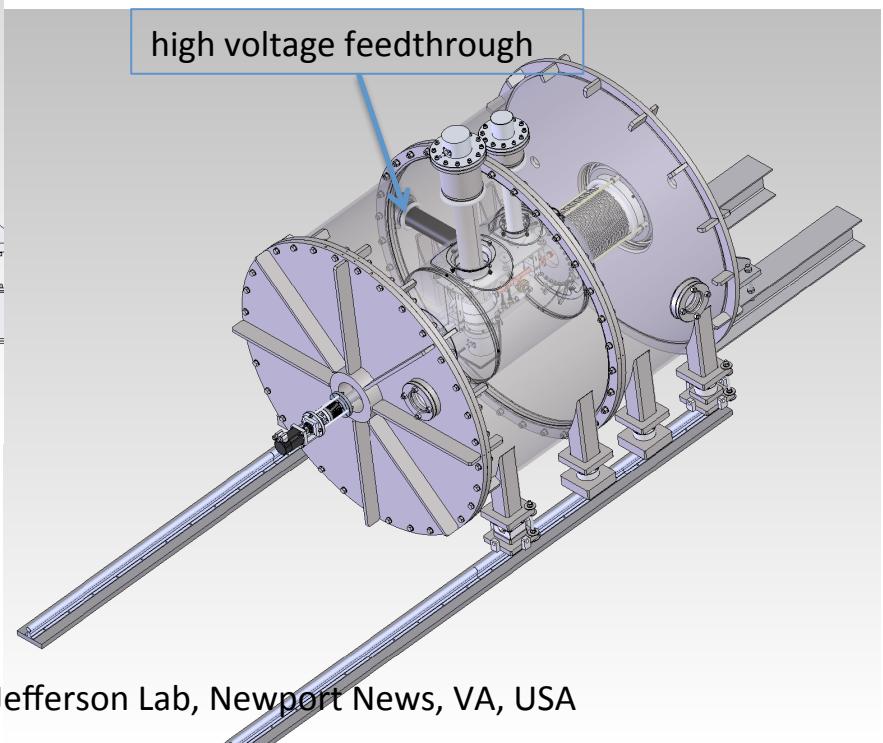
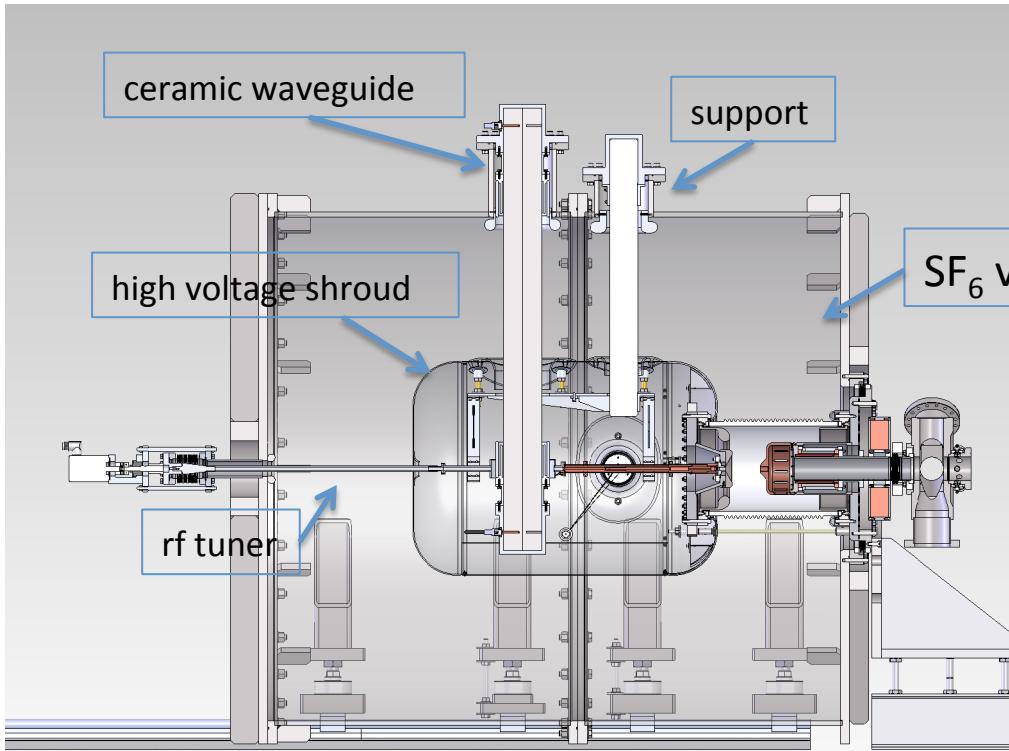
# TRIUMF ARIEL rf modulated thermionic gun



- rf modulation frequency **650** MHz,
  - pulse length +/- **16°** (137 ps).
  - average current **10** mA
  - charge / bunch **15.4** pC
  - kinetic energy **300** keV
  - normalized transverse emittance  
**~5**  $\mu$ m
  - duty factor for macro pulsing  
**0.1-100%** (3 W-3 kW)
- **thermionic source with rf-modulation applied to grid**

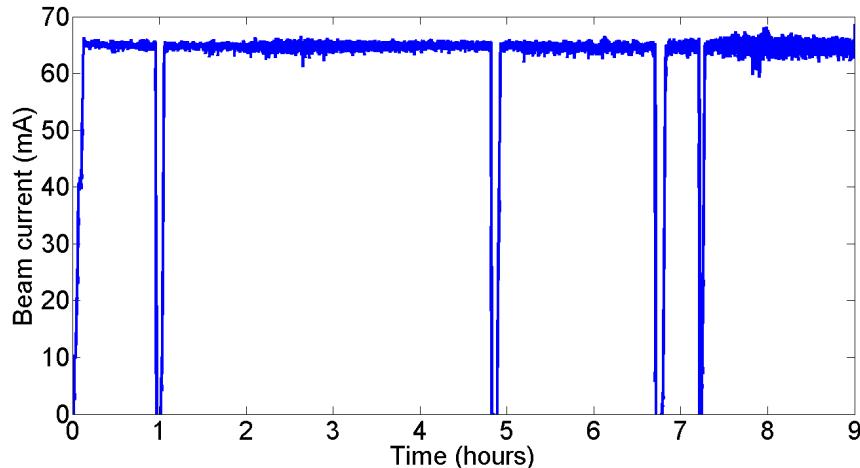
Friedhelm Ames, TRIUMF , presented at EIC14, March 17-21, Jefferson Lab, Newport News, VA, USA

# TRIUMF ARIEL rf-modulated thermionic gun

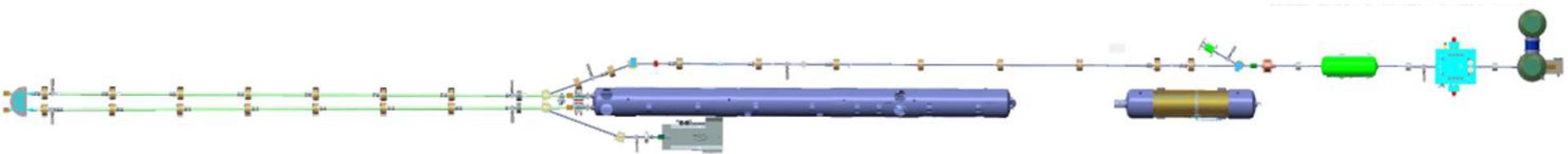
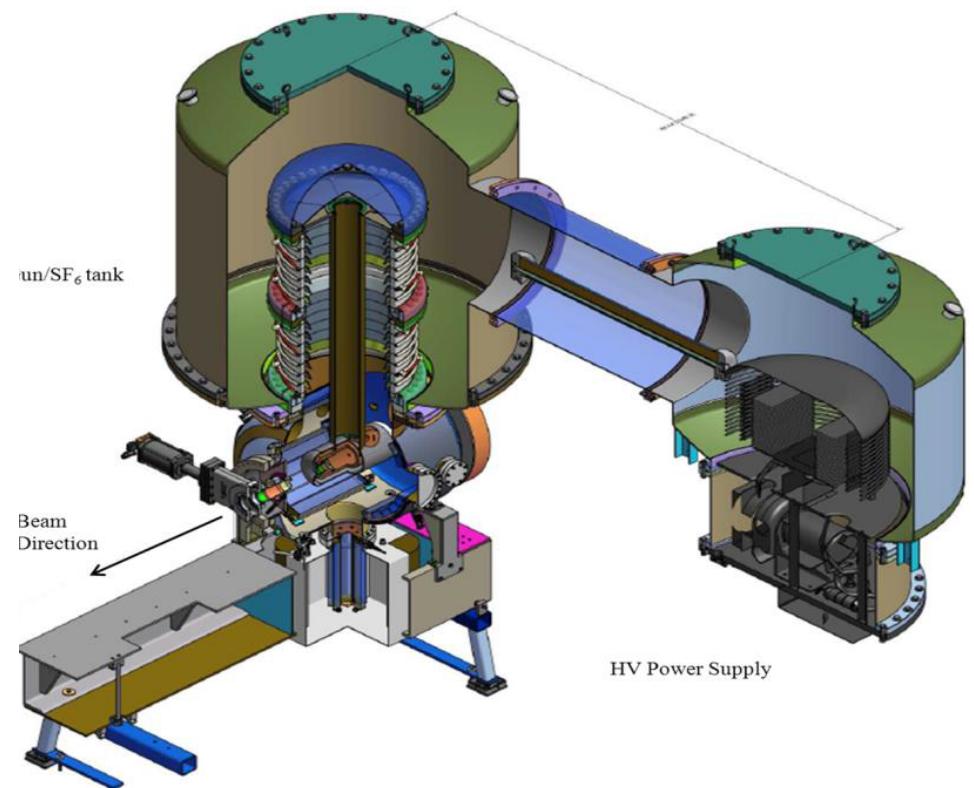


Friedhelm Ames, TRIUMF , presented at EIC14, March 17-21, Jefferson Lab, Newport News, VA, USA

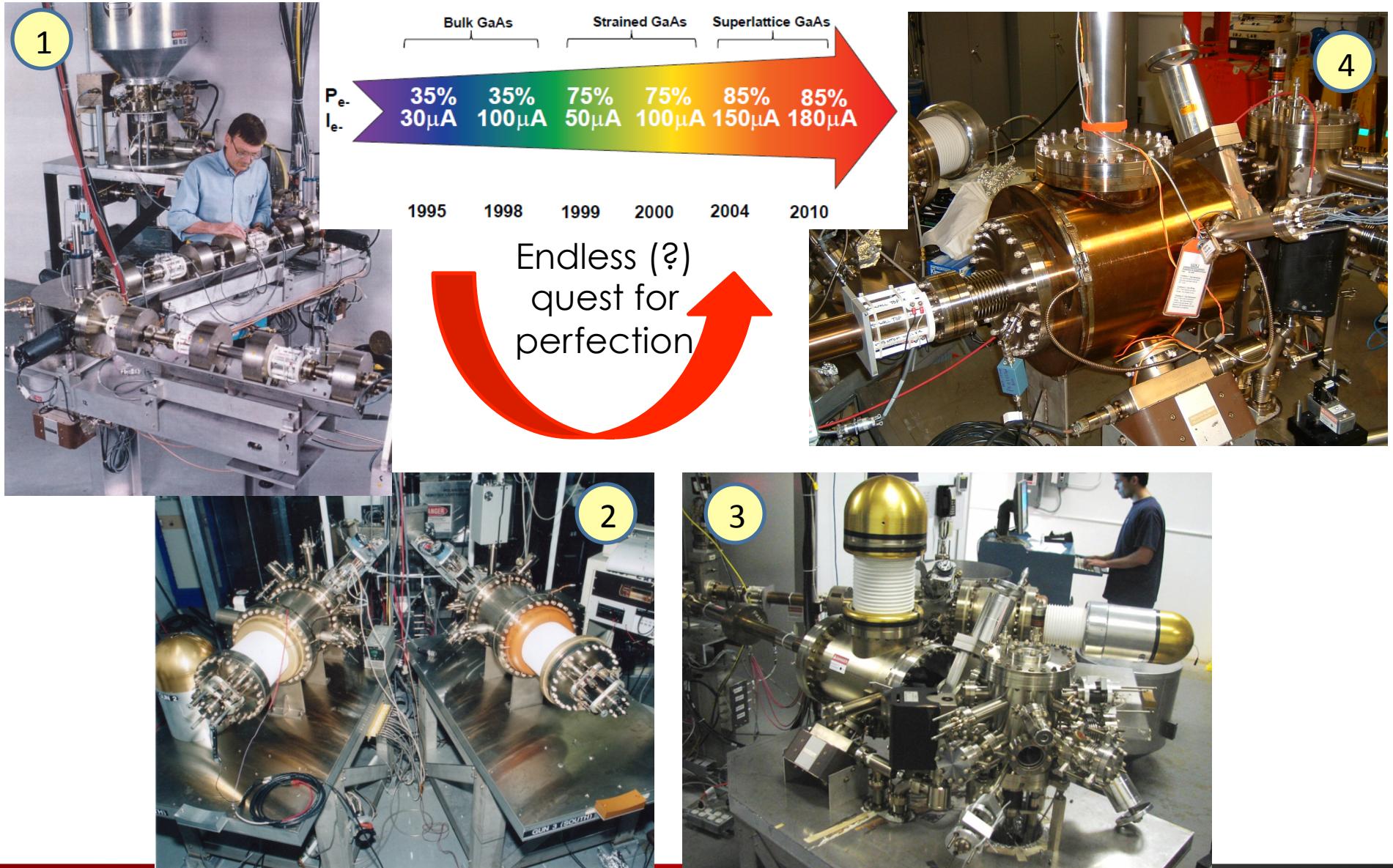
# Low-Energy RHIC electron Cooling (LEReC)



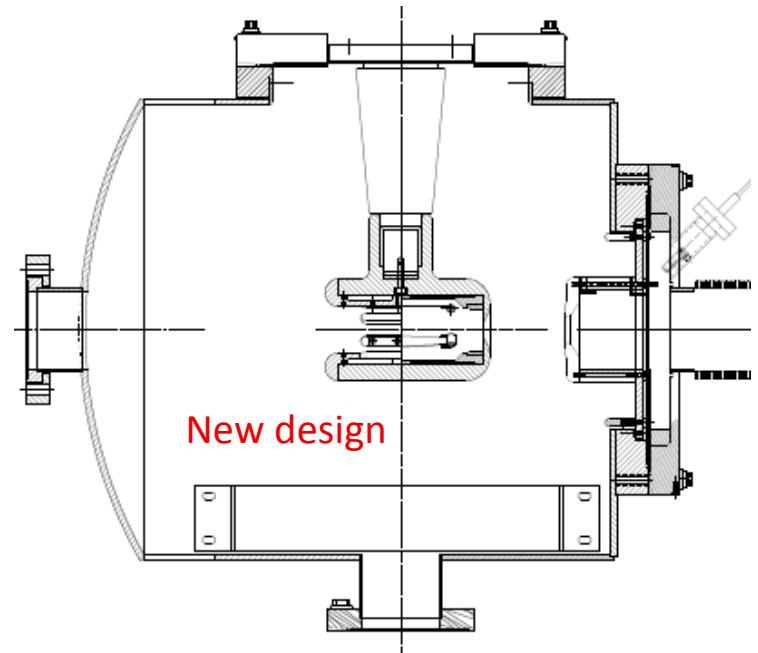
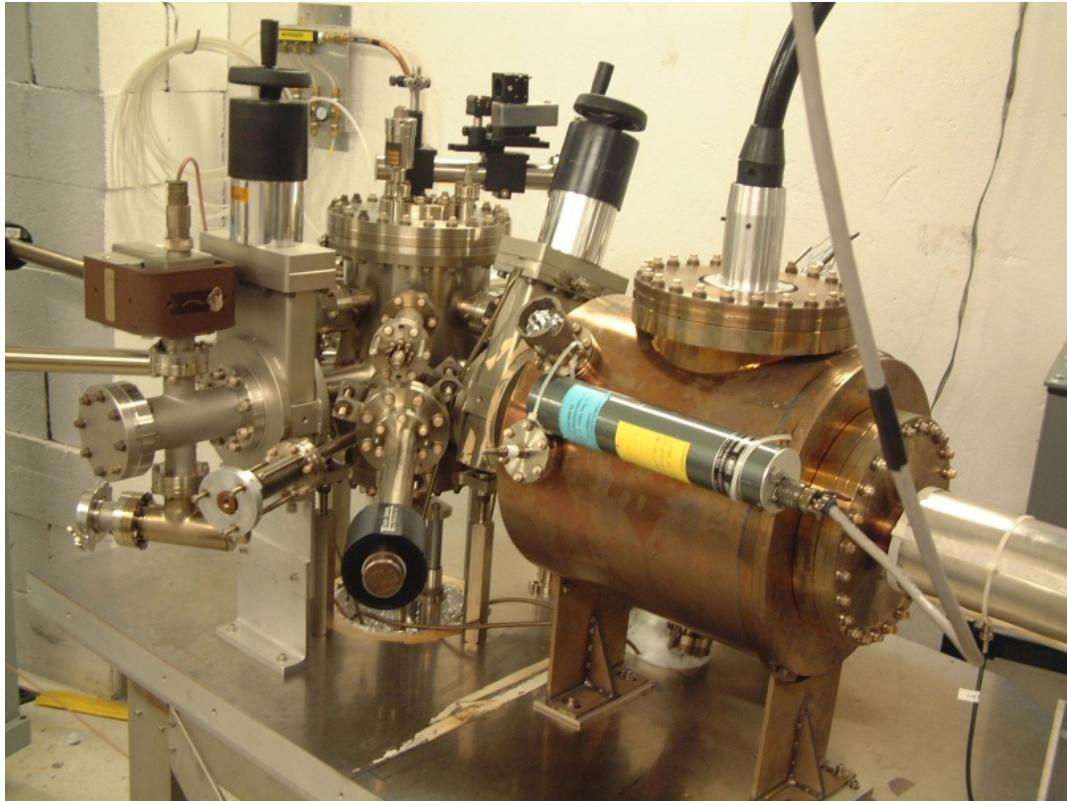
Cornell DC high voltage photogun



# Always Tweaking the Design



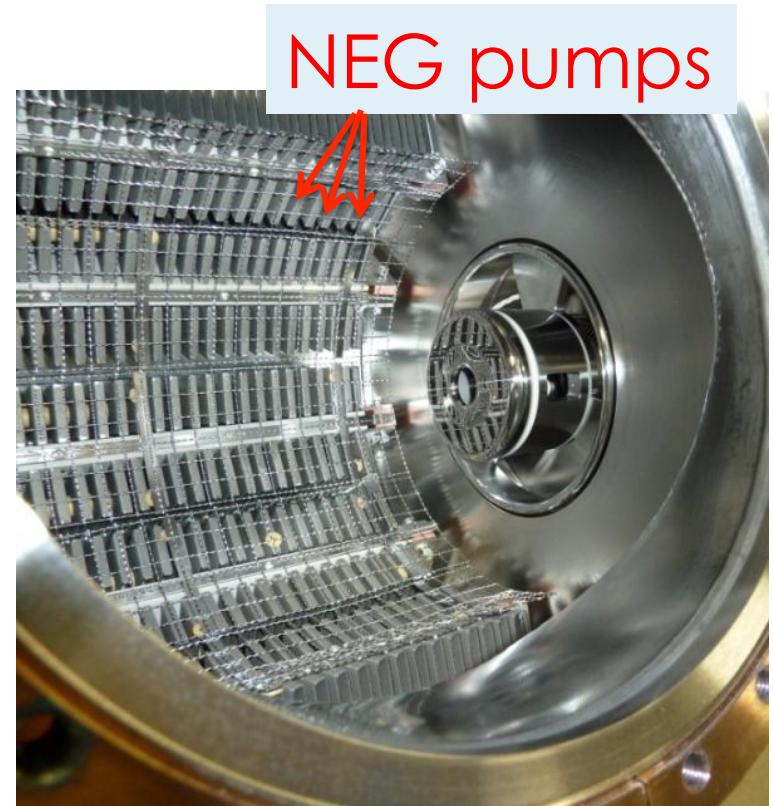
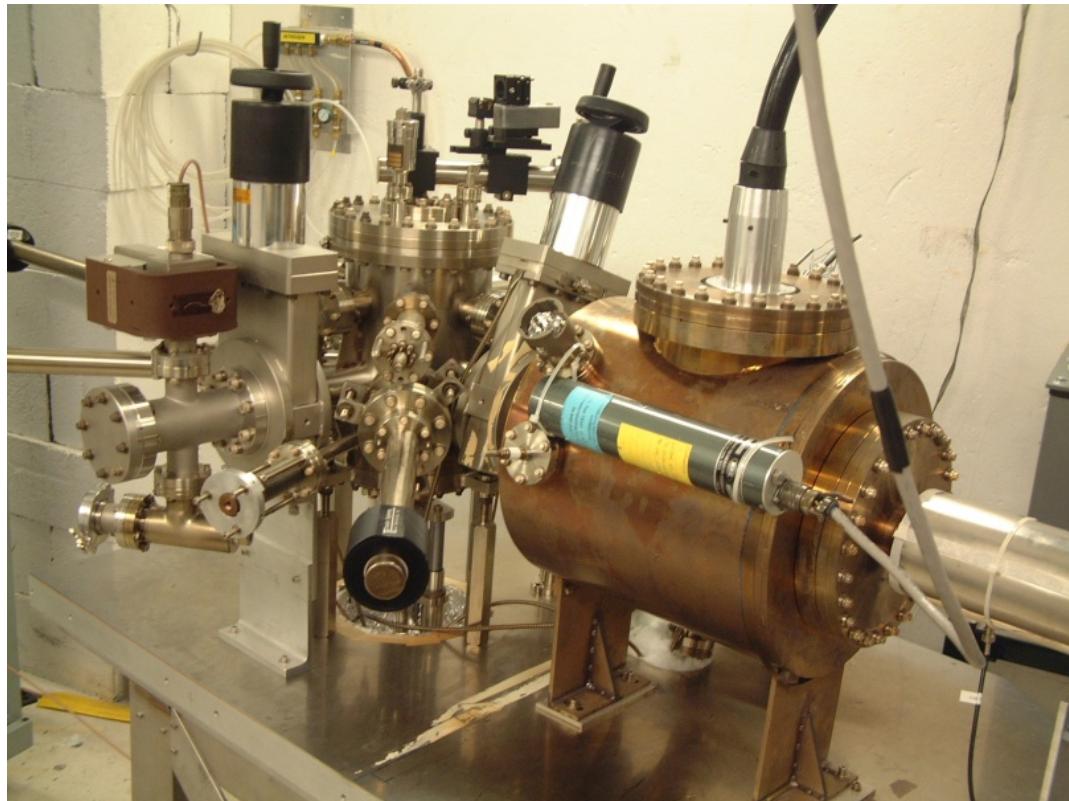
# The CEBAF - ILC 200kV Inverted Gun



Our “Load-locked” GaAs photogun:

- Gun Vacuum ~ mid to low  $10^{-12}$  Torr
- Beamlime vacuum could be improved...

# The CEBAF - ILC 200kV Inverted Gun



Our “Load-locked” GaAs photogun:

- Gun Vacuum ~ mid to low  $10^{-12}$  Torr
- Beamlime vacuum could be improved...

# Benefits of Higher Gun Voltage

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- I. Reduce space-charge-induced emittance growth, maintain small transverse beam profile and short bunch-length. In other words, make a “stiff” beam right from the gun
- II. Reduce problems associated with Surface Charge Limit (*i.e.*, QE reduction at high laser power)
- III. Prolong Charge Lifetime (?)
- IV. Compact, less-complicated and less-expensive injector

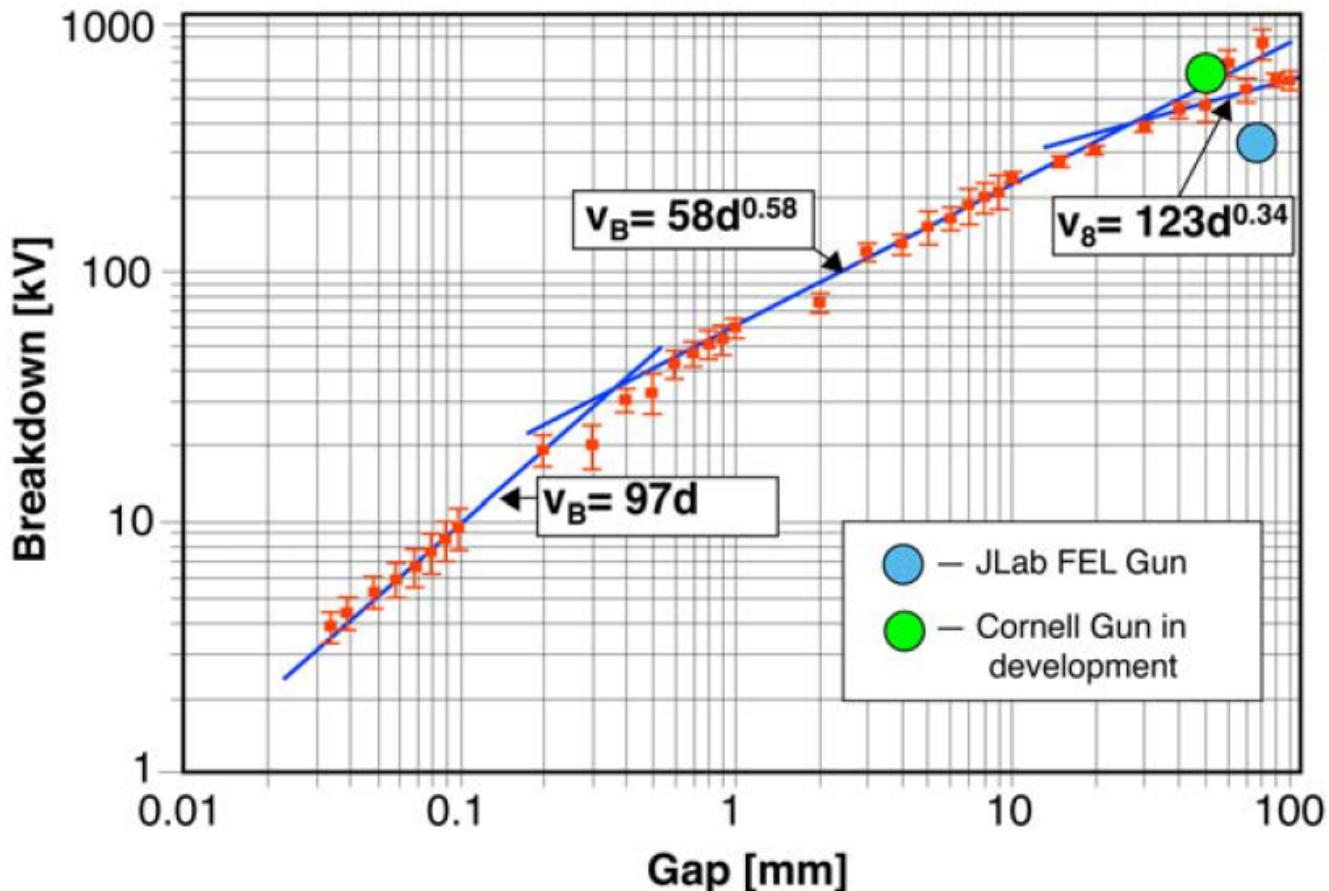
BIGGEST OBSTACLE: Field Emission and HV Breakdown... which lead to bad vacuum and photocathode death

# FIELD EMISSION

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- Sources of Field Emission: micro-protrusions, contamination on surface, material defects and impurities, ionization of desorbed gas, etc.,
- Material choices: hardness, work function, grain structures and grain boundaries, electrical conductivity, thermal conductivity
- Surfaces: generally people assume smooth is better than coarse, although experiments indicate smooth does not guarantee “good”
- Mostly, people assume 5 MV/m is “easy” - we want to operate at 10 MV/m or higher

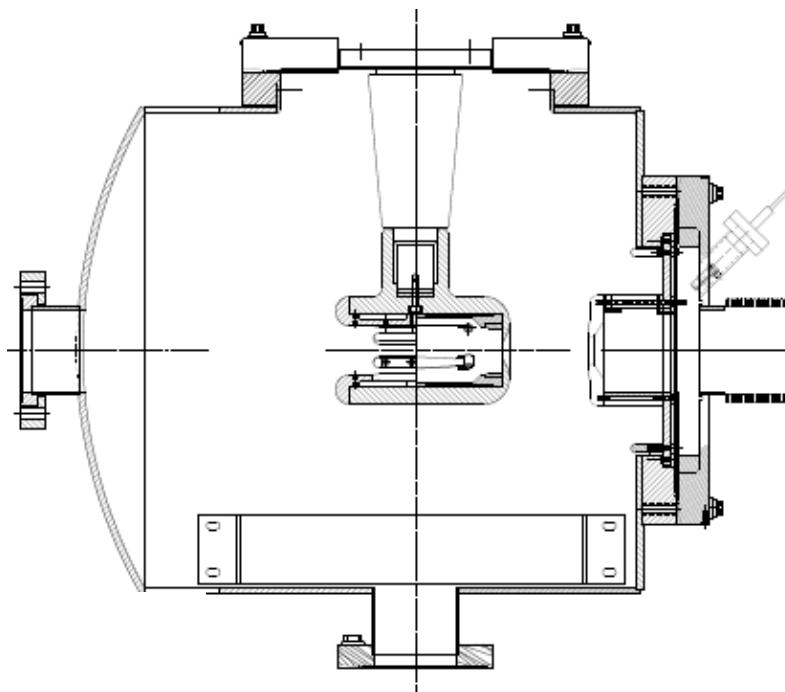
# BREAKDOWN IN VACUUM



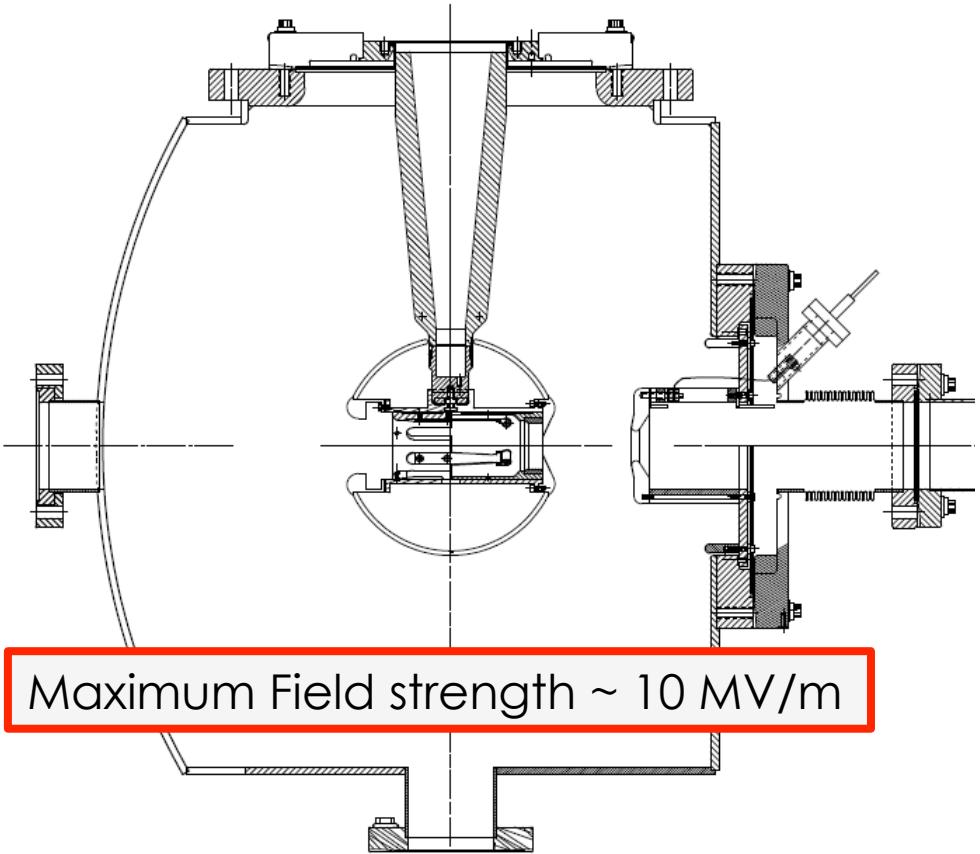
*From Paul G. Slade*

**Figure 7:** High voltage holdoff versus vacuum gap dimension.

# 350 kV PHOTOGUN



CEBAF 200kV  
Inverted Gun  
“R28” insulator

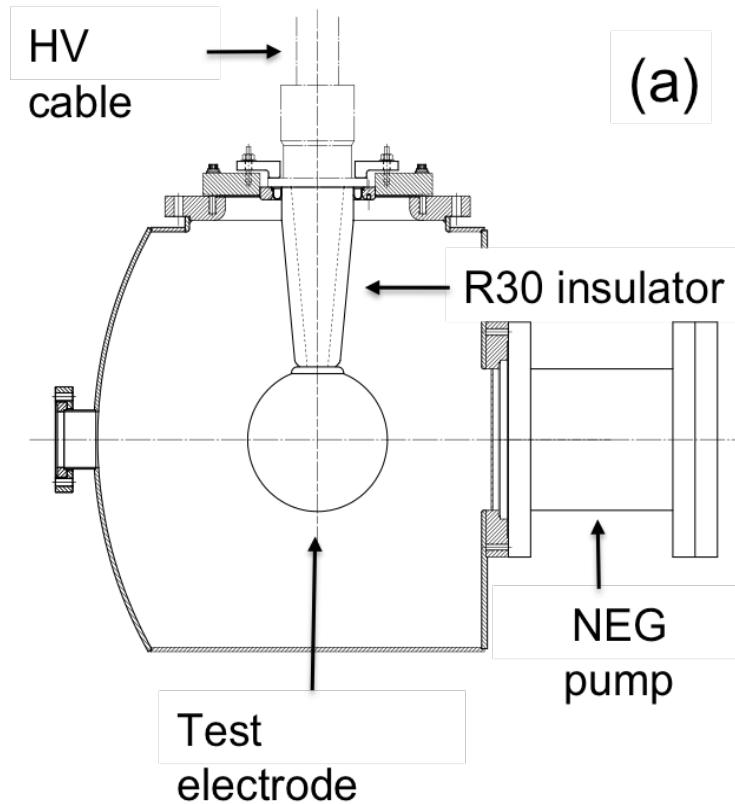


Maximum Field strength ~ 10 MV/m

- Longer “R30” insulator
- Spherical electrode
- Thin NEG sheet - move ground plane further away

# BUILDING THE 350 kV GUN

- Start with “dummy” electrodes and test different insulators and cathode screening electrode



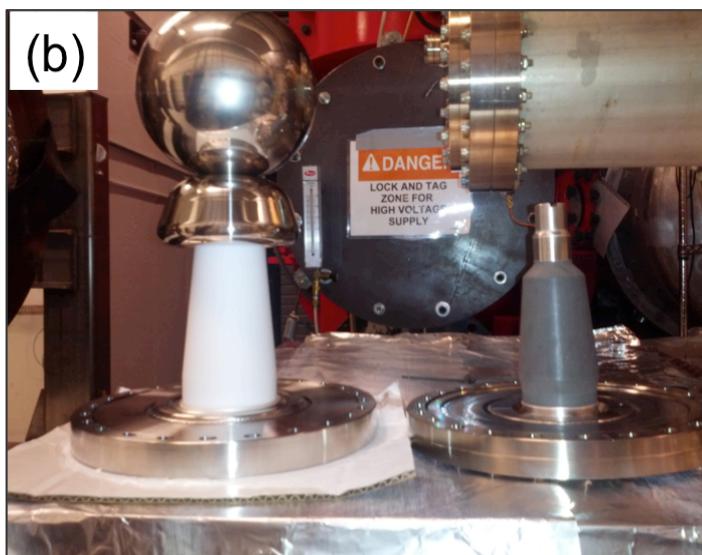
(a)



(b)

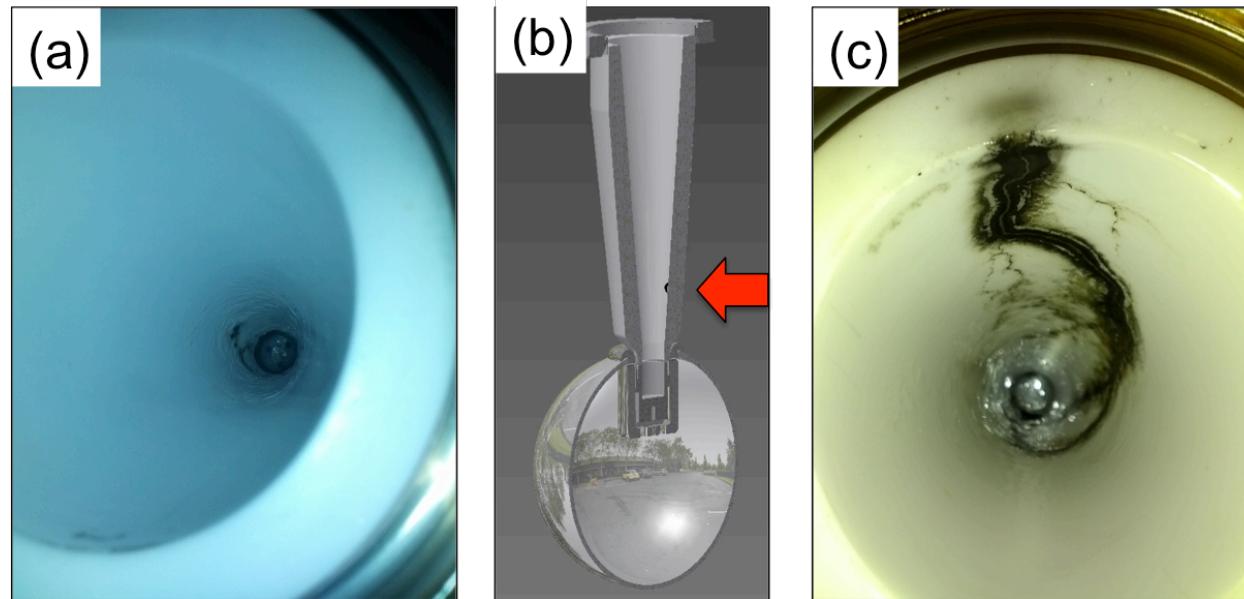
# INSULATORS AND SCREENING ELECTRODE

- Longer R30 insulators, conventional alumina
- Short R28 insulator, bulk resistivity, mildly conductive
- Longer R30 insulator, bulk resistivity, mildly conductive
- ZrO-coated R30 insulator, also mildly conductive
- dummy electrode with a screening electrode (shed)



# BREAKDOWN AT CABLE/INSULATOR INTERFACE

- Problems at the cable junction, atmosphere side



- Note: Field emission was managed via krypton-processing. i.e., voltage first applied with  $\sim 10^{-5}$  Torr krypton added to gun chamber

# SUMMARY OF TESTS

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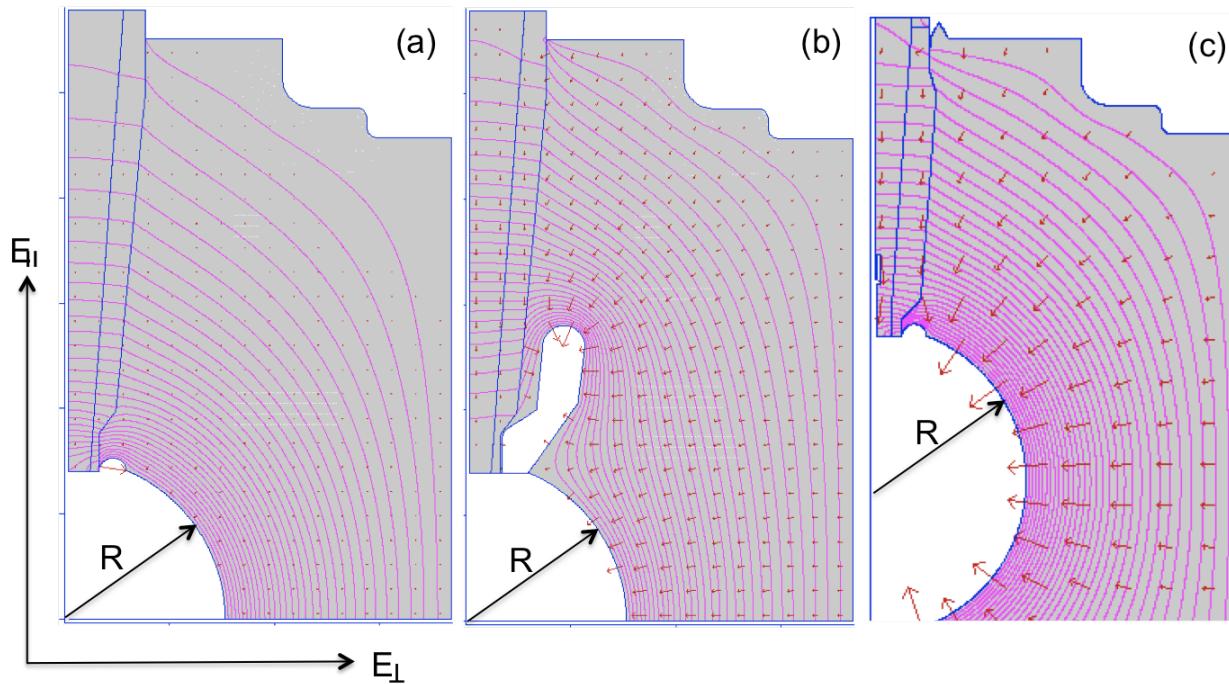
- Two and 1/2 configurations reached our voltage goal

Insulator type	Length (cm)	Transversal resistivity (Ohm-cm)	Dielectric constant $\epsilon_1/\epsilon_0$	Maximum voltage (kV)	Performance
R30 sample 1	20	$5.0 \times 10^{15}$	9.1	329	Breakdown and puncture near high voltage end
R30 sample 2	20	$5.0 \times 10^{15}$	9.1	300	Breakdown
R30 with additional screening electrode	20	$5.0 \times 10^{15}$	9.1	375	370 kV with krypton 4-hr soak, 350 kV in vacuum 4-hr soak. Significant field emission in both cases
R30 ZrO-coated	20	$5.0 \times 10^{15}$	9.1	340	Breakdown and puncture near ground end 360 kV with krypton 1-hr soak, 350 kV in vacuum 5-hr soak, 2 times Minimal field emission in both cases
R28 doped	13	$7.4 \times 10^{15}$	8.4	360	Breakdown originating at high voltage end and puncture near ground end
R30 doped	20			360	

Work of Carlos Hernandez-Garcia and the “team”

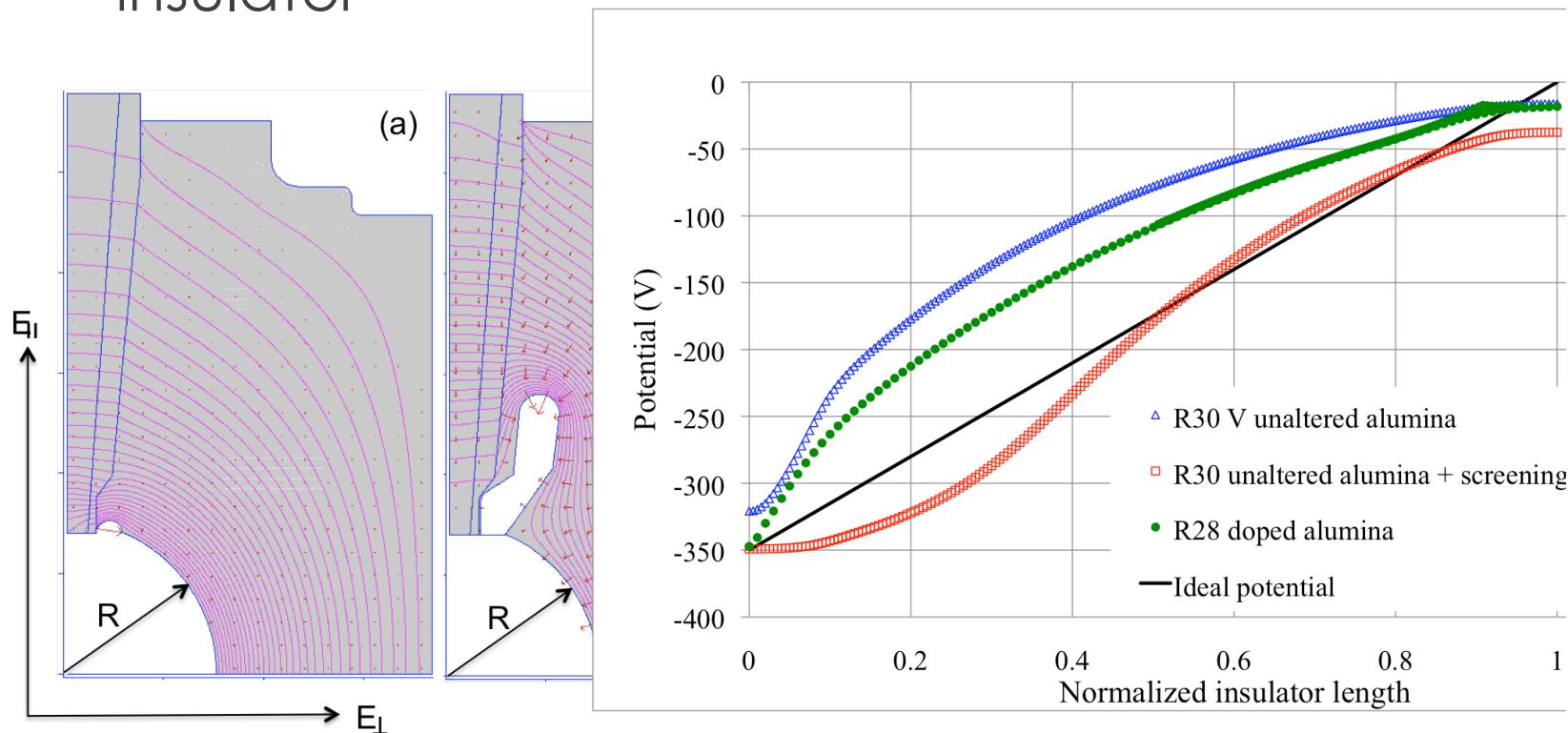
# LINEAR POTENTIAL DROP

- Want a linear potential gradient along length of the insulator



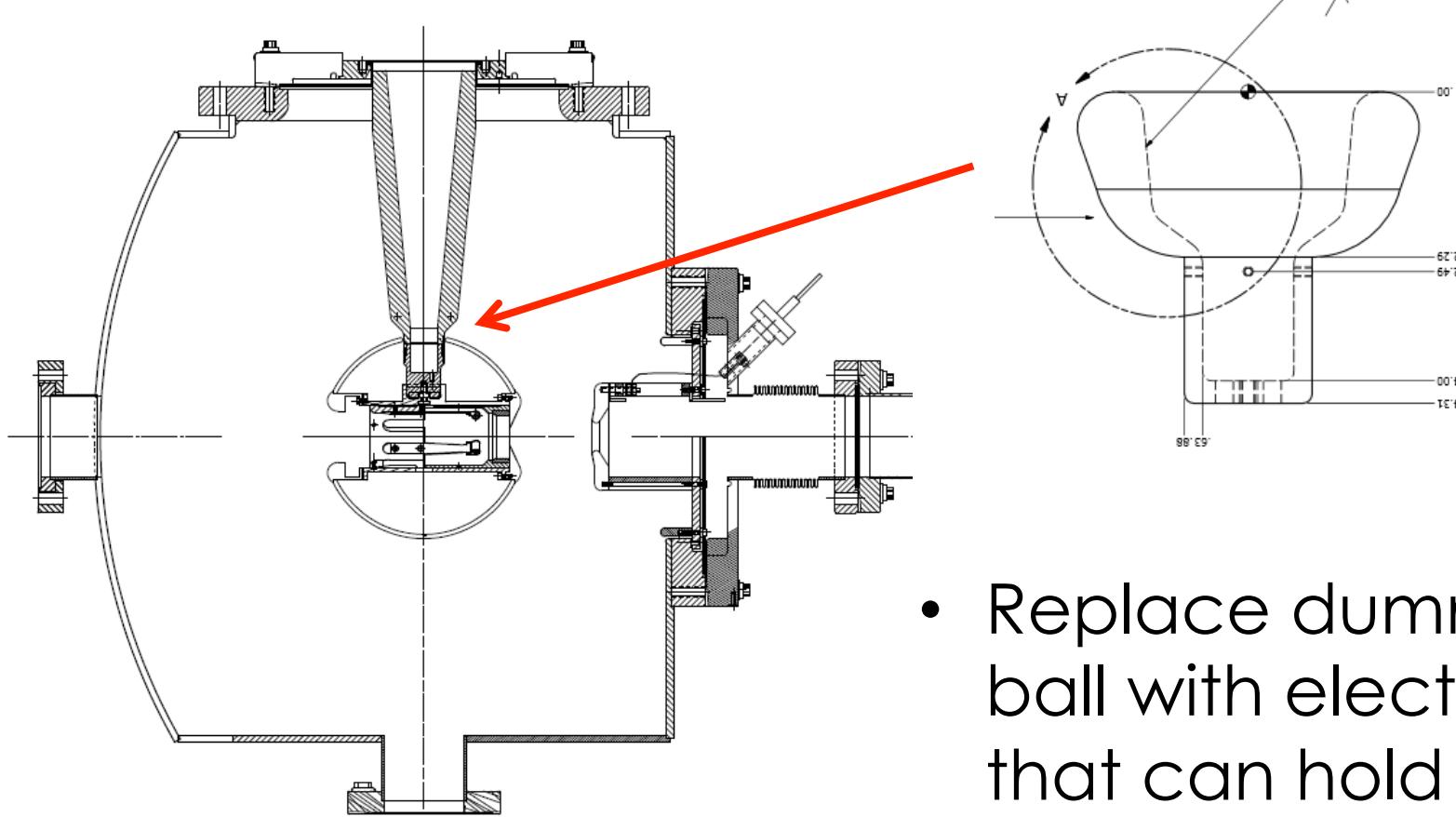
# LINEAR POTENTIAL DROP

- Want a linear potential gradient along length of the insulator



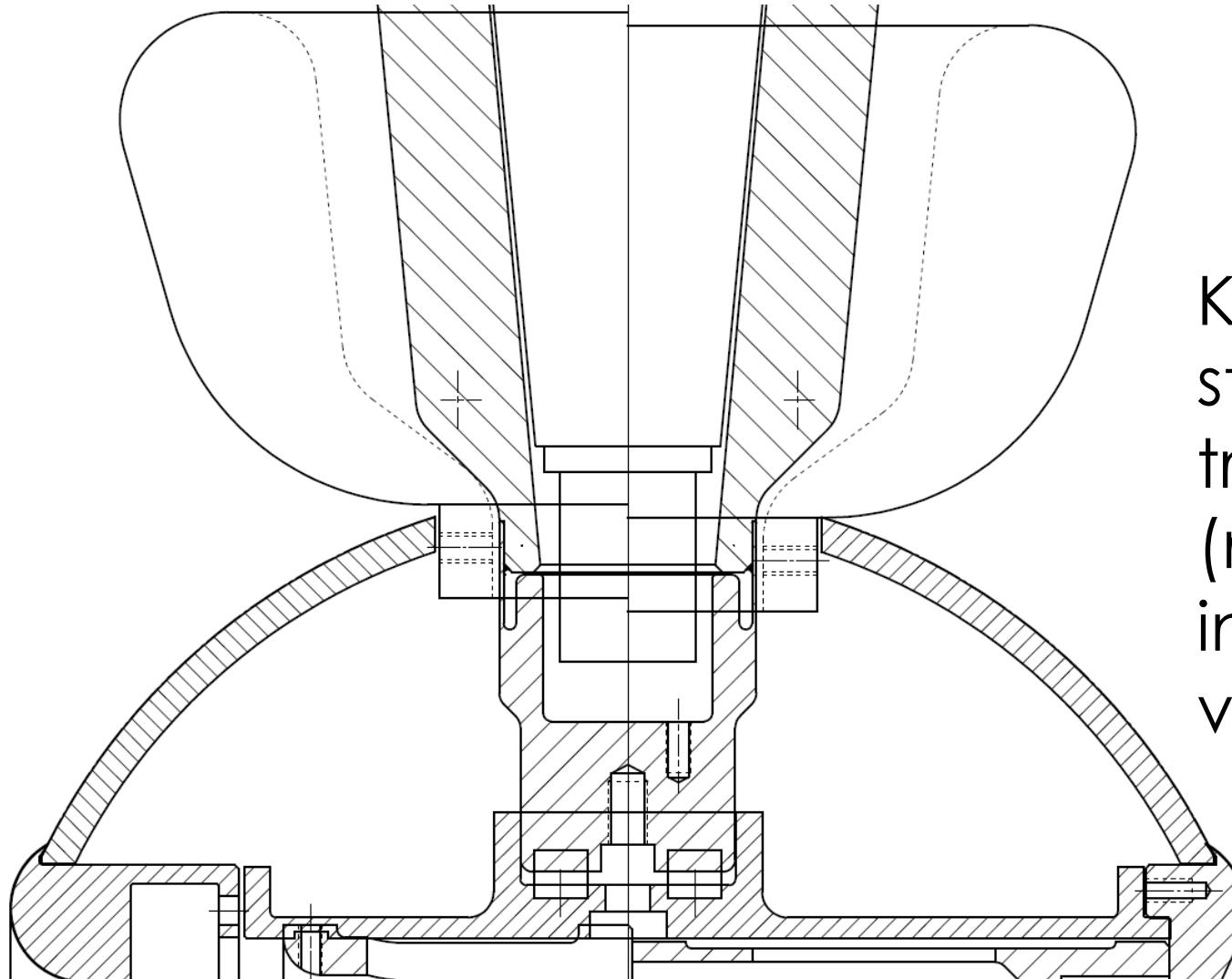
- Note - POISSON does not accurately model the mildly-conductive feature of the black insulator

- Plan Y: Combine the two features that provided incremental success: screening electrode and doped black R30 insulator



- Replace dummy ball with electrode that can hold photocathode

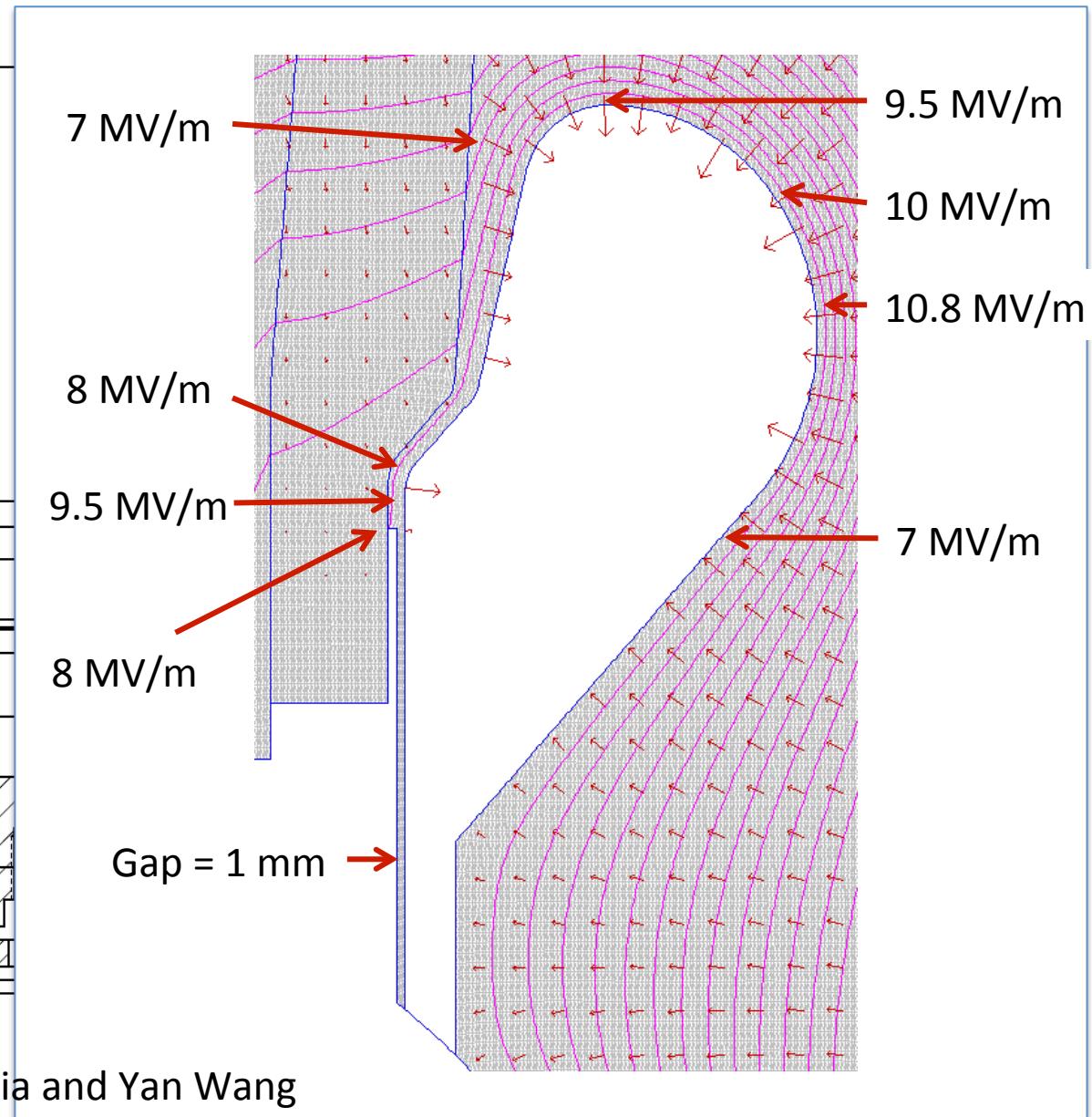
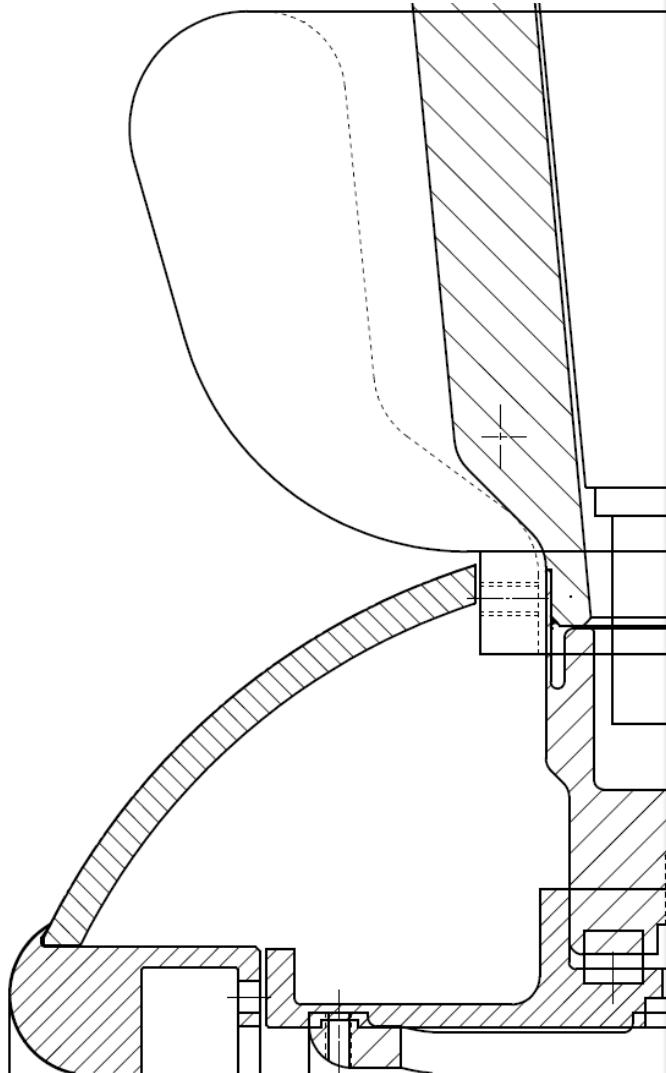
# The gap between shed and insulator



Keep field strength low at triple point (metal, insulator, vacuum)

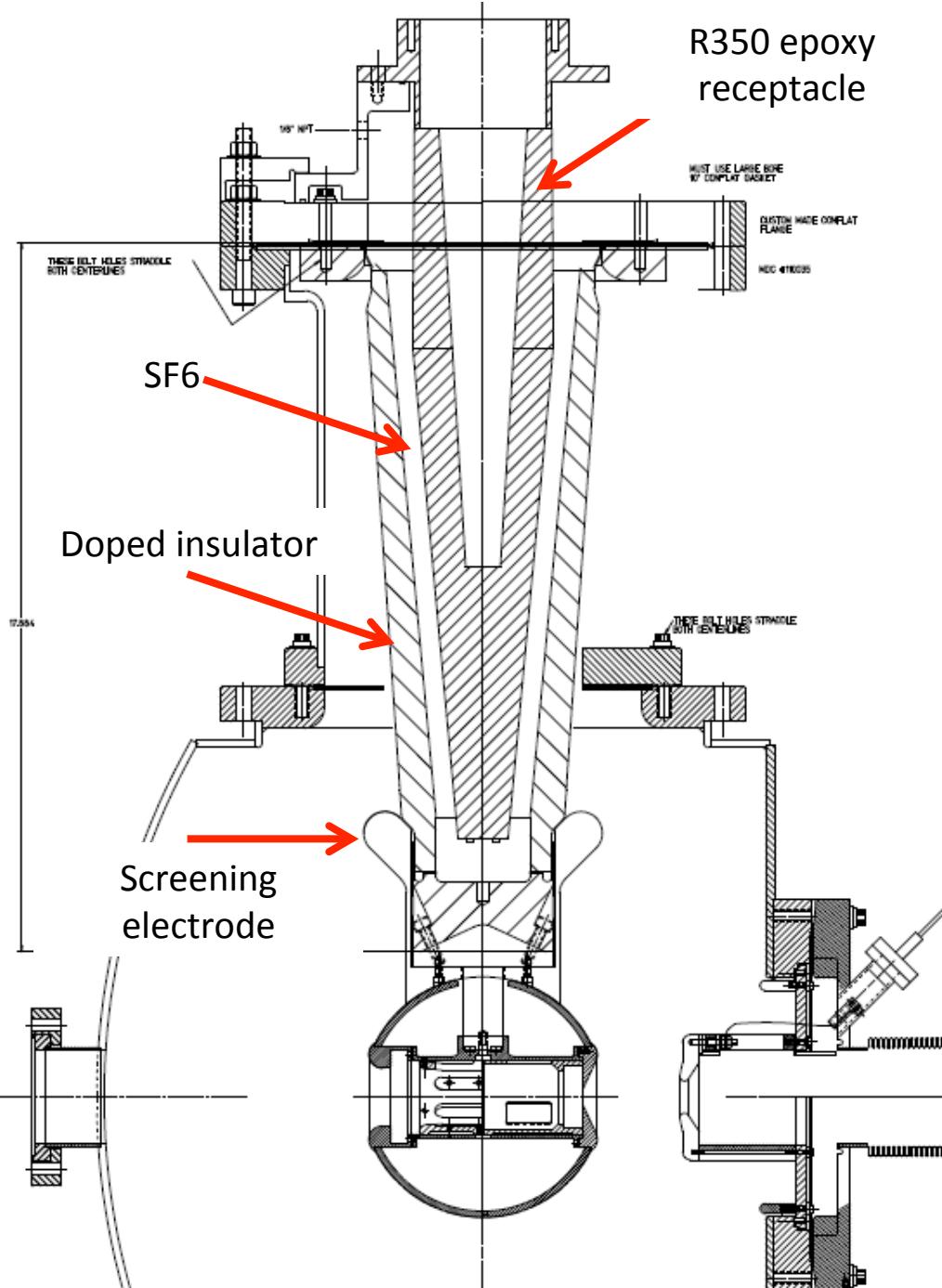
Work of Carlos Hernandez-Garcia and Yan Wang

# The gap between shed and insulator

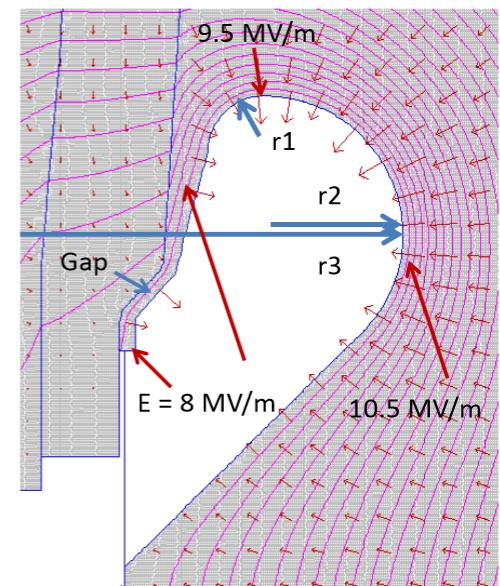


# Plan Z

- Combination of doped insulator and shed, SF6 and epoxy receptacle, plus added length
- the screening electrode, a good design...



- $r_1 = 1 \text{ cm}$
- $r_2 = 2.5 \text{ cm}$
- $r_3 = 9.5 \text{ cm}$
- 3 mm gap



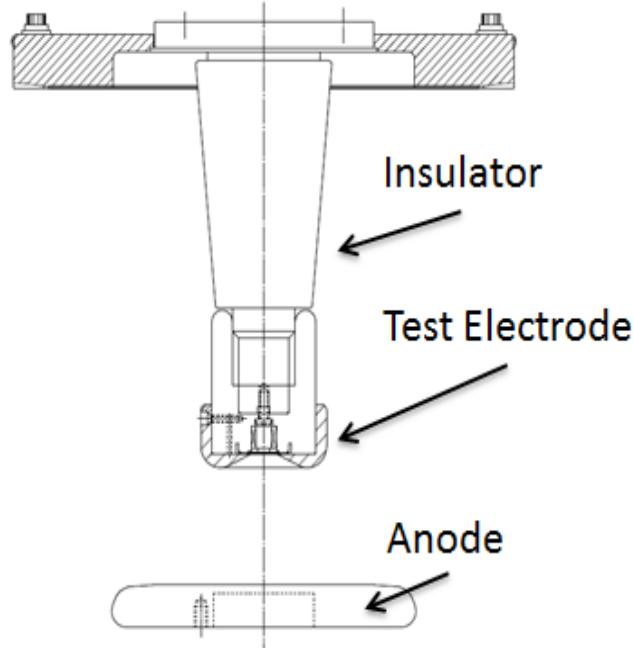
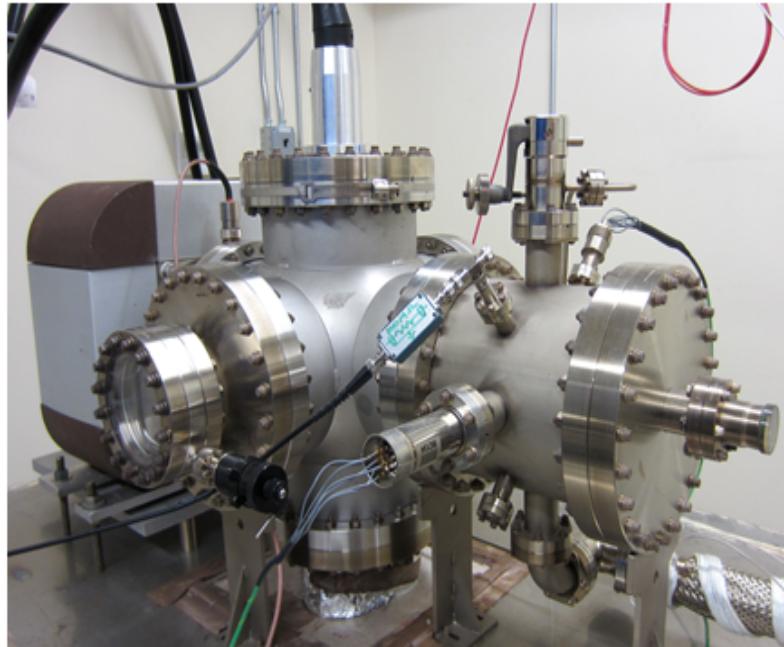
Work of Yan Wang

# FIELD EMISSION: THINGS WE'VE BEEN STUDYING

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- Fowler-Nordheim Theory: a good place to start, but it will disappoint ...
- Diamond-paste polished stainless steel
  - Is it necessary to have such a smooth surface?
- Gas conditioning: an essential tool
- Electropolished stainless steel: speed the process?
- Barrel-polished stainless steel: another option
- BCP-d niobium: expensive
- TiN-coated aluminum: promising...
- 900 °C degas, CO<sub>2</sub> snow, high pressure rinsing...

# FIELD EMISSION TEST STAND



- Spellman -225kV supply, small “R28” inverted insulators, variable cathode/anode gap from to 10 to 50mm, field strength to  $\sim 20$  MV/m
- Build a test stand that resembles an actual gun (tests with small gaps and high field strength but low voltage, don't appear to be very useful)

# DIAMOND-PASTE POLISHING

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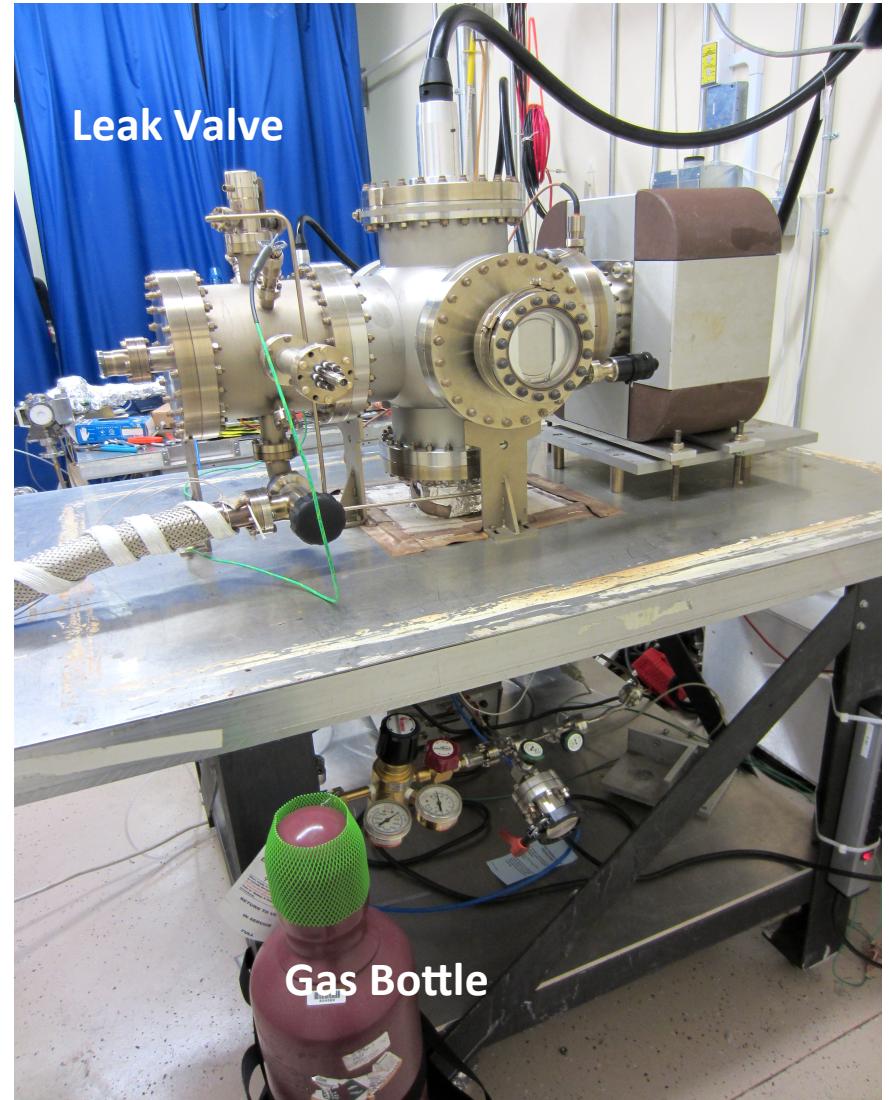
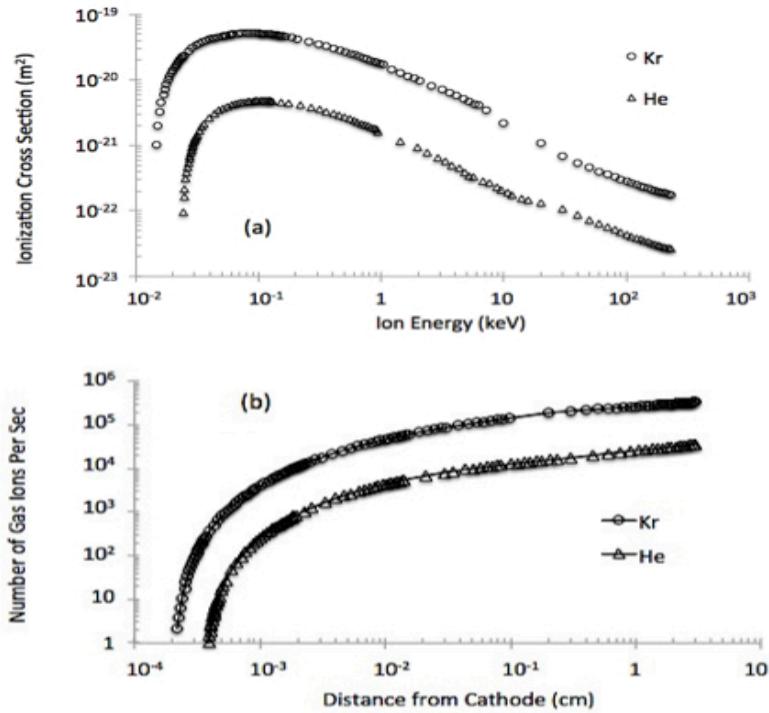
- Receive the electrode from the machine shop with “32” surface finish
- Silicon carbide polishing with 300 grit paper to remove obvious visible scratches
- Solvent cleaning in ultrasonic bath of alkali solution
- Silicon carbide polishing with 600 grit paper
- Solvent cleaning in ultrasonic bath of alkali solution
- Polish with 6mm grit
- Ultrasonic clean
- Polish with 3mm grit
- Ultrasonic clean
- High pressure rinsing (1200 psi) for 20 minutes with ultrapure de-ionized water with resistivity > 18 MWcm.
- High temperature (900°C) vacuum degas for one hour

# DIAMOND-PASTE POLISHING

---

- Receive the electrode from the machine shop with “32” surface finish
  - Silicon carbide polishing with 300 grit paper to remove obvious visible scratches
  - Solvent cleaning in ultrasonic bath
  - Silicon carbide polishing with 100 grit paper
  - Solvent cleaning in ultrasonic bath
  - Cleaning in acetone bath
  - High pressure rinsing (1200 psi) for 20 minutes with ultrapure de-ionized water with resistivity > 18 MWcm.
  - High temperature (900°C) vacuum degas for one hour
- Two months later and the electrode is ready for high voltage!  
Maybe it will work!?

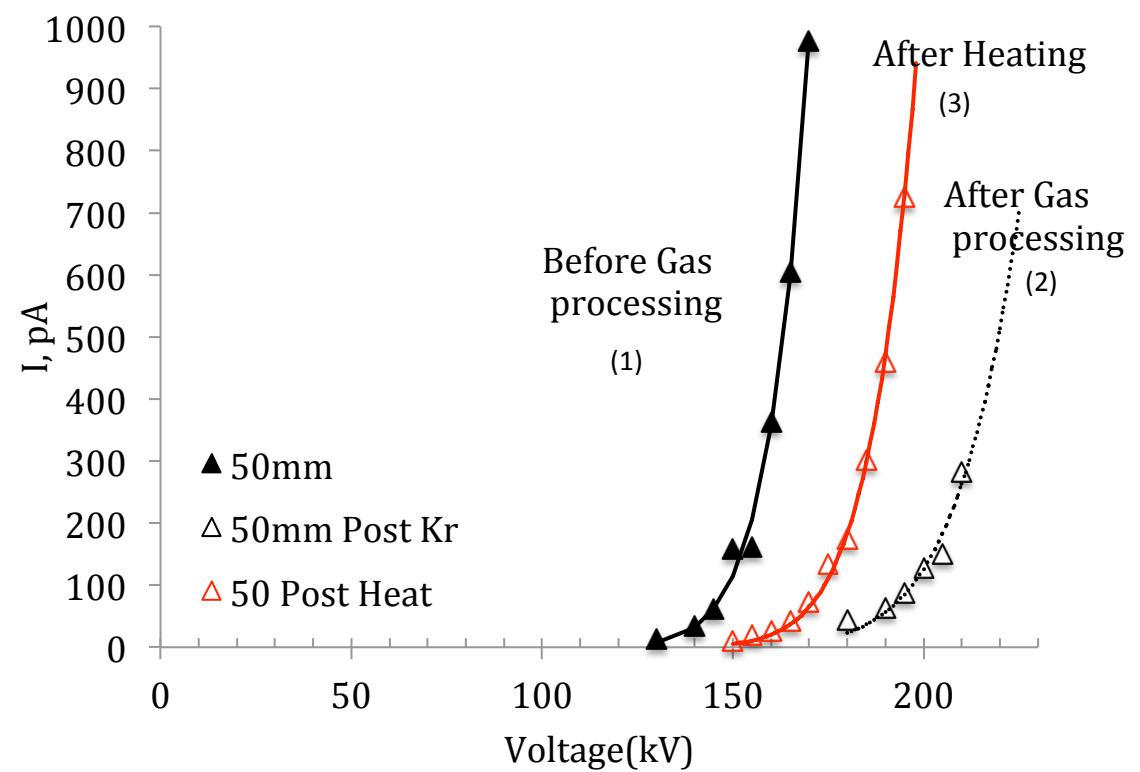
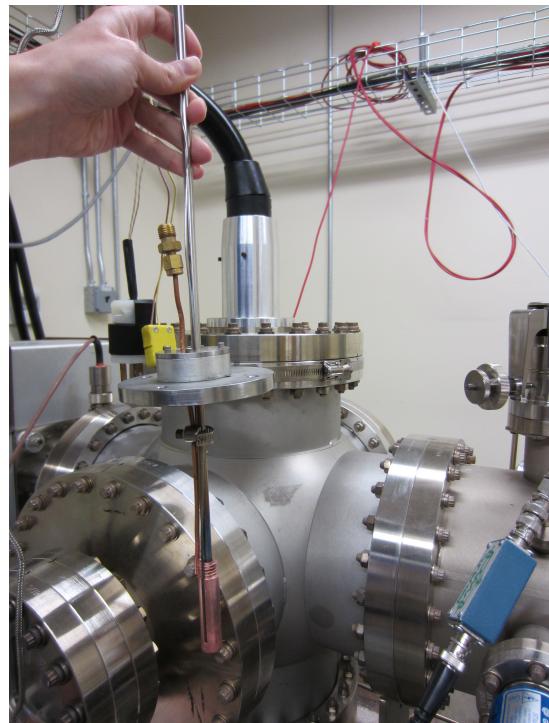
# GAS CONDITIONING



- Field emission ionizes inert gas
- Ions bombard electrode, hopefully near field emitter, which can be sputtered away
- And ions get implanted, increasing work function

# WHAT DOES GAS CONDITIONING Do?

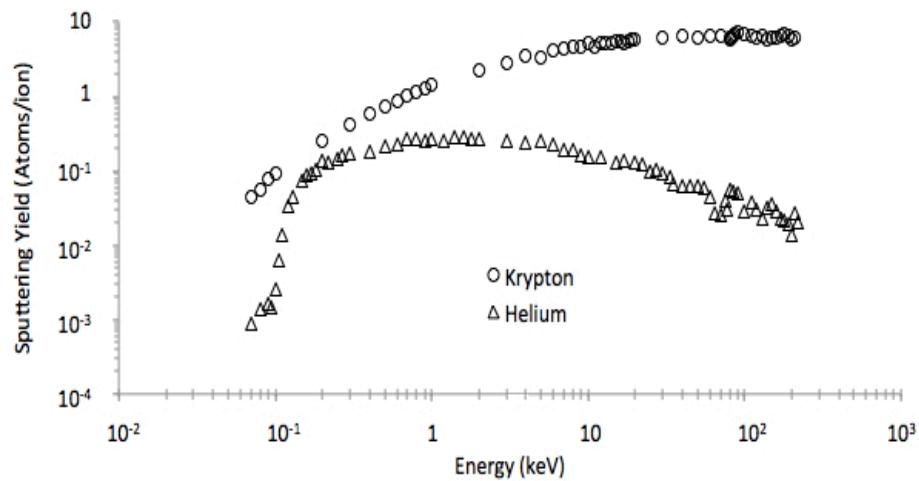
Benefits of implantation are reversible



Work of M. BastaniNejad, E. Forman, C. Hernandez-Garcia

# WHAT DOES GAS CONDITIONING Do?

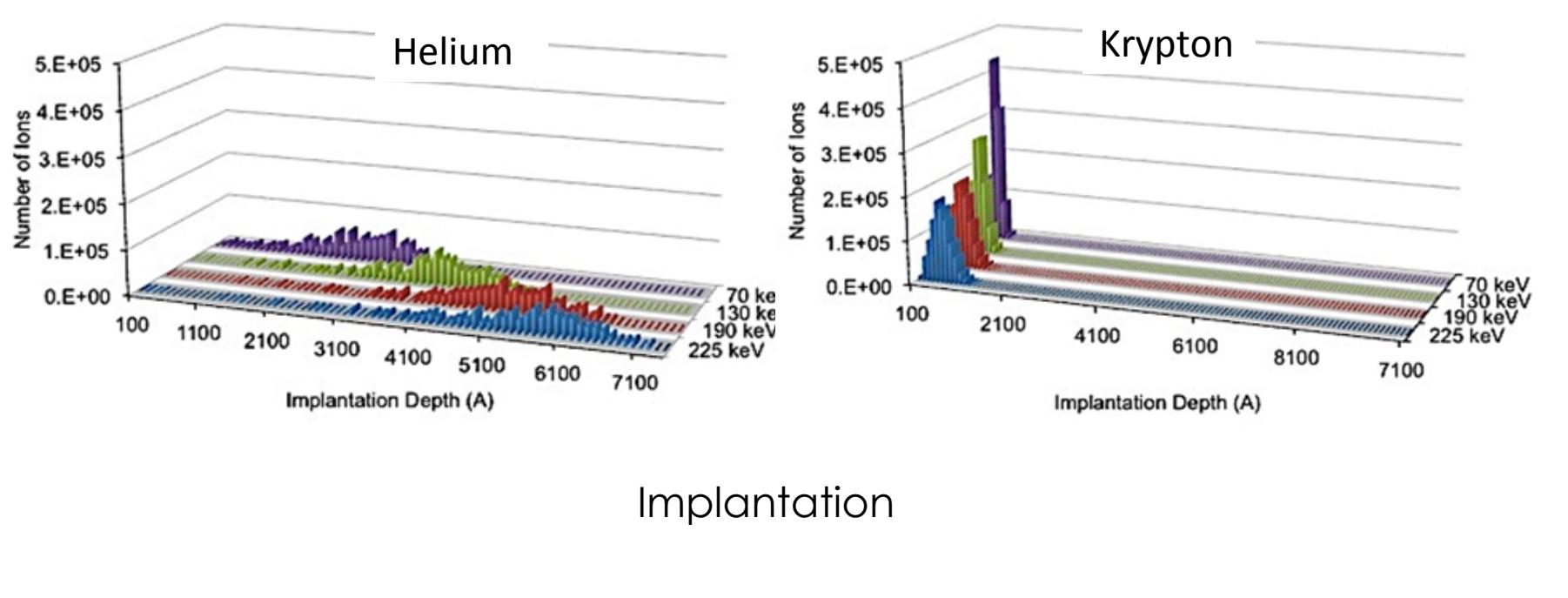
## Sputtering and Implantation



Sputtering Yield

# WHAT DOES GAS CONDITIONING Do?

## Sputtering and Implantation



# WHAT DOES GAS CONDITIONING Do?

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## Sputtering and Implantation

- Helium: want a shallow implantation depth, so helium works best when FE turns ON at lower voltages, and/or with small gaps (10 to 20mm), don't expect much sputtering
- Krypton: can work at any voltage, good for larger gaps (30 to 50mm), sometimes too much sputtering creates a new field emitters

# A POWERFUL TECHNIQUE

- Gas conditioning can turn a BAD electrode into a GOOD electrode
- TURN OFF ion pump
- NEG pumps don't pump inert gas
- Set voltage to excite field emitter
- Add gas at  $10^{-5}$  Torr, apply voltage and watch for sharp decrease in FE current

Turn on Field Strength (MV/m) at 100pA , Before Gas Processing vs. Gaps

Gap (mm)	304L#1	304L#2	316LN#1	316LN#2
50	6.4	4.9	>12.6	8.7
40	6.6	5.4	>13.8	8.1
30	6.2	5.5	>15	9.1
20		6.6	15	10.5

Turn on Field Strength (MV/m) at 100pA , After Gas Processing vs. Gaps

Gap (mm)	304L#1	304L#2	316LN#1	316LN#2
50	>12.6	>12.6	>12.6	>12.6
40	>13.8	>13.8	>13.8	>13.8
30	13.6	13.5	>15	12.9
20		14.4	17.3	14.1

Perhaps 316L is better than 304L?

# BACKUP SLIDES

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- Thank You

# DIAMOND-PASTE POLISHED STAINLESS STEEL

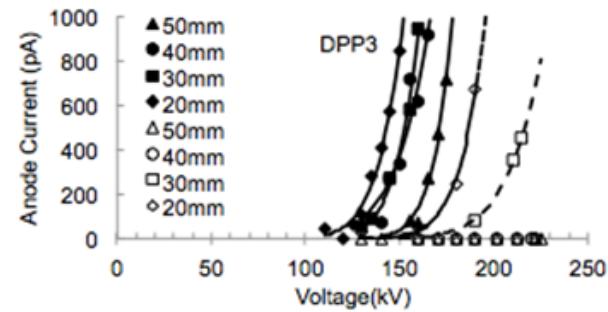
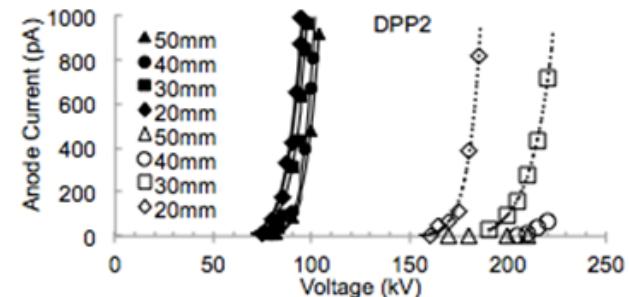
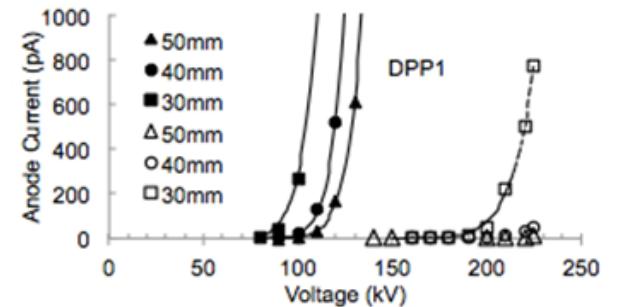
- Variable performance is common
- Favorable response to gas conditioning

Turn on Field Strength (MV/m) at 100pA, Before Gas Processing vs. Gaps

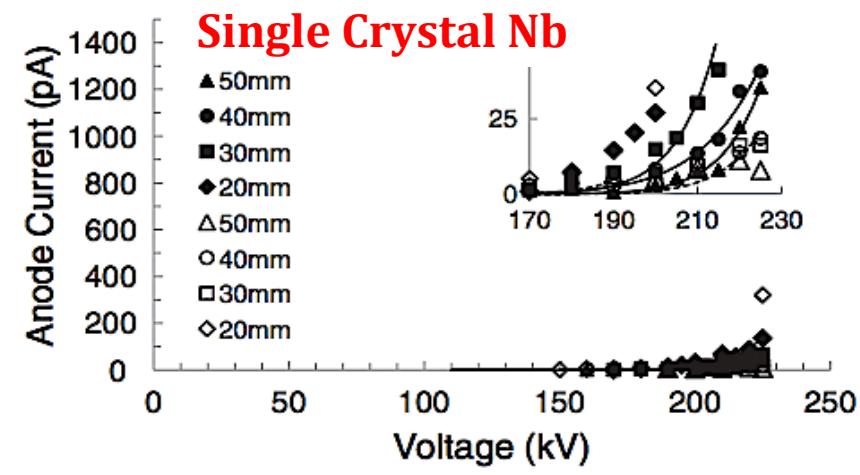
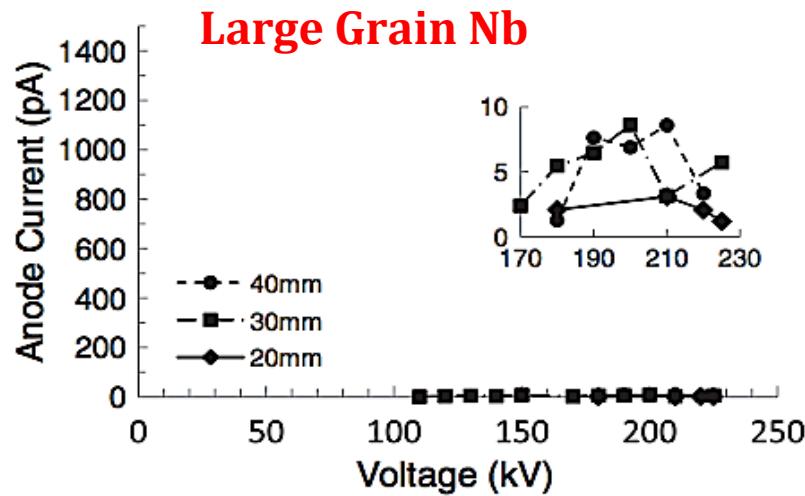
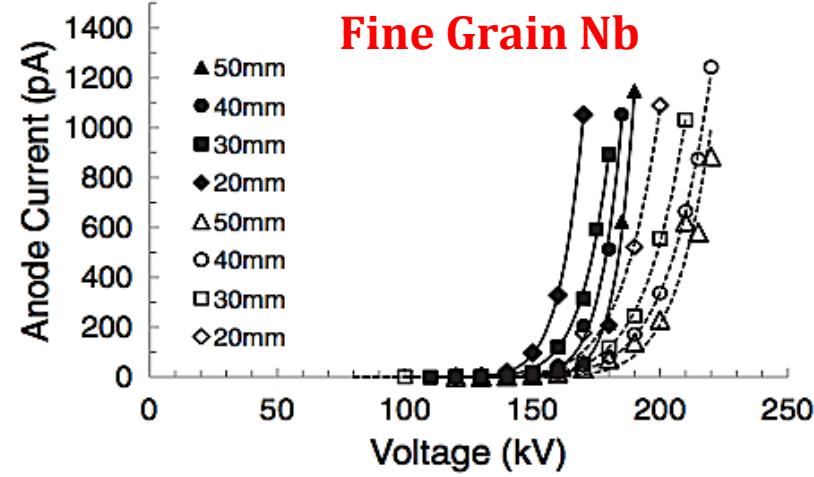
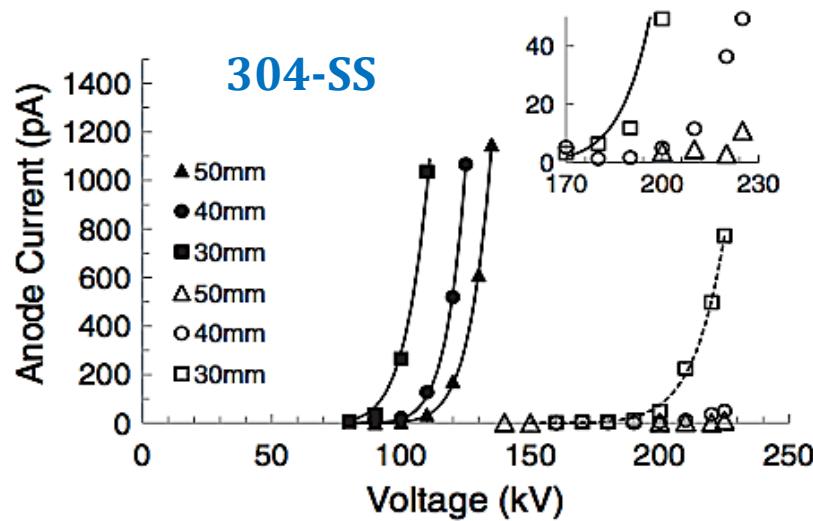
Gap(mm)	EP1	EP2	EP3	DPP1	DPP2	DPP3
50	10.9	7.3	>12.6	6.4	4.9	8.7
40	11.1	8.1	>13.8	6.6	5.4	8.1
30	11.4	8.7	14.8	6.2	5.5	9.1
20	11.3	10.5	17.5		6.6	10.5

Turn on Field Strength (MV/m) at 100pA, After Gas Processing vs. Gaps

Gap(mm)	EP1	EP2	EP3	DPP1	DPP2	DPP3
50	8.2	9.2	>12.6	>12.6	>12.6	>12.6
40	9.1	9.9	>13.8	>13.8	>13.8	>13.8
30	9.8	10.5	>15.1	13.6	13.5	12.9
20	11.3	12.8	>18.7		14.4	14.1



# I TO V CURVES FOR NIOBIUM



# BUFFERED CHEMICAL POLISHING OF NIOBIUM

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- Receive the electrode from the machine shop with “32” surface finish
- Silicon carbide polishing with 600 grit paper, if necessary, to remove obvious visible scratches
- Solvent cleaning in ultrasonic bath of alkali solution
- Buffered-chemical polishing to remove ~ 100 mm material
- High pressure rinsing (1200 psi) for 20 minutes with ultrapure de-ionized water with resistivity > 18 MWcm.
- High temperature (900°C) vacuum degas for one hour

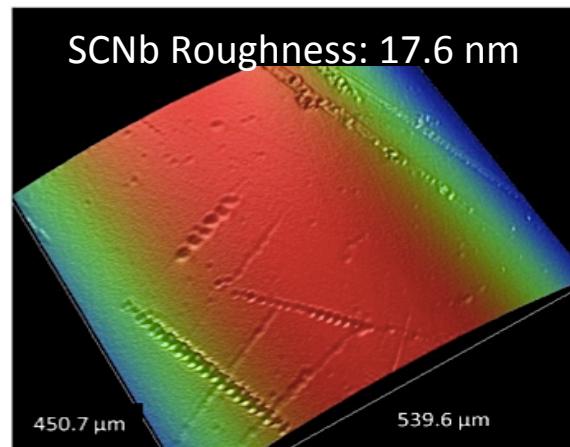
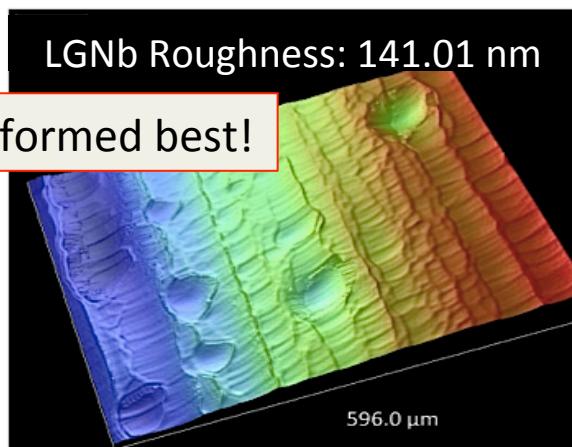
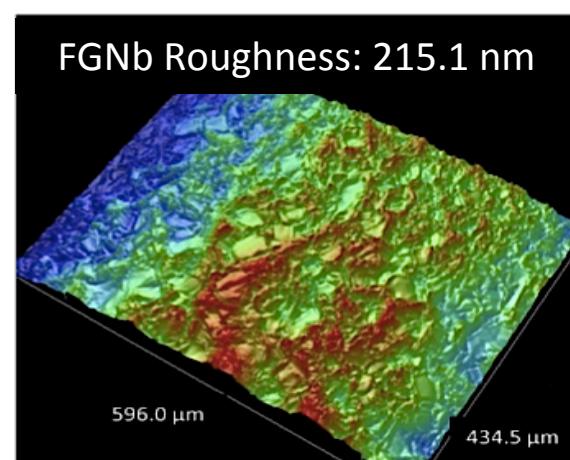
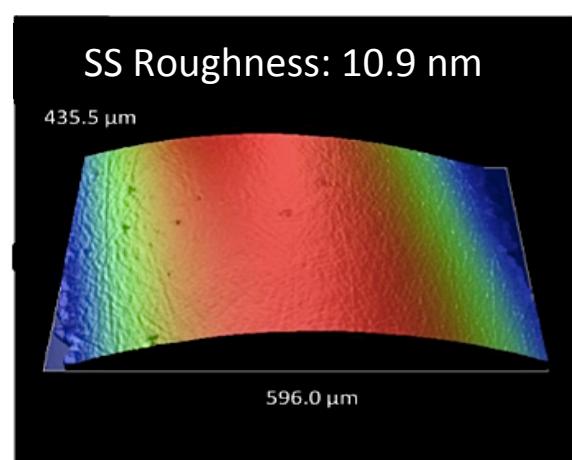
# FE RESULTS OF BCP-ED NIOBIUM

- Field strength at which the electrode exhibited 100pA of field emission, post krypton gas conditioning
- “>” symbol....the electrode did not produce 100pA of field emission

	FGNb1	FGNb2	SCNb1	SCNb2	LGNb1	LGNb2	DPP-SS1	DPP-SS2
50mm	11.8	10.7	>12.6	>12.6	>12.6	>12.6	>12.6	10.7
40mm	11.5	11.2	>13.8	>13.8	>13.8	>13.8	>13.8	10.0
30mm	10.8	12.0	>15.0	13.1	>15.0	15.0	13.6	9.9
20mm	10.4	14.1	>18.7	12.3	>18.7	17.5	No data	No data

# NIOBIUM ELECTRODES

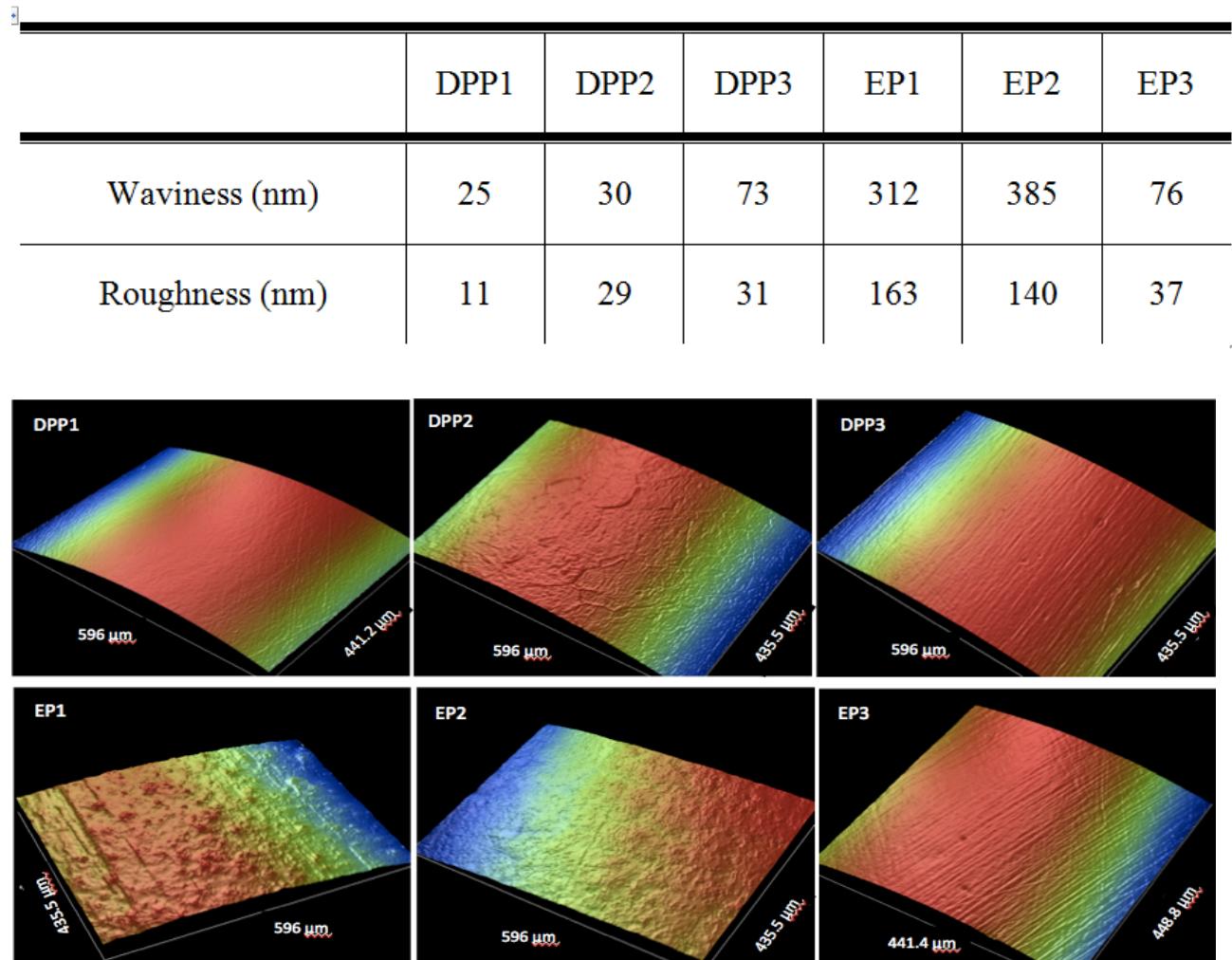
- More evidence that there's more to field emission than topography



This one performed best!

# ELECTROPOLISHED STAINLESS STEEL

- Can we avoid time-consuming diamond-paste polishing?
- Start with three test electrodes having different surface finish, and send them to commercial electropolishing company

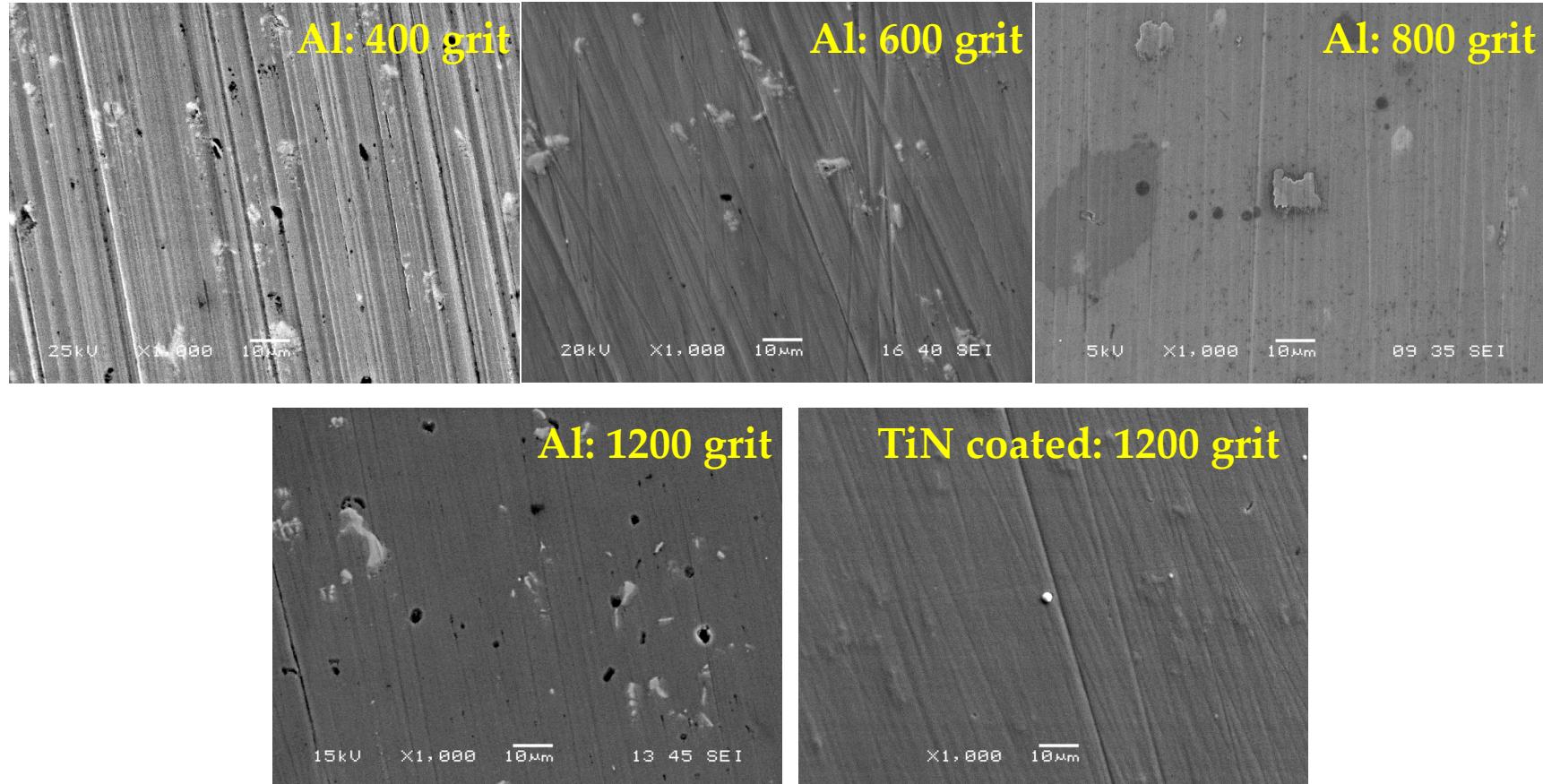


# TiN-COATED ALUMINUM

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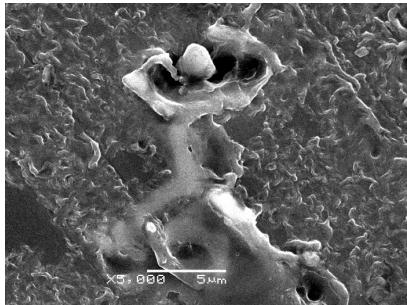
- Aluminum is cheap and easy to machine
- Takes just hours to polish to mirror-like finish with silicon-carbide paper
- Good thermal conductor, compared to steel, a nice feature when gun provides high current
- We used a “boutique” vendor to coat our small electrodes
- Can an industrial TiN-coating provide the same benefit? Need to test

# SURFACE IMAGES AL AND TiN-AL

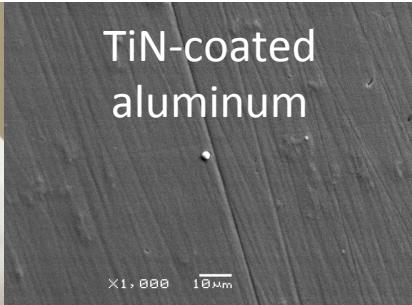


Note, the black spots are voids and defects, not particulate contamination from sand paper polishing

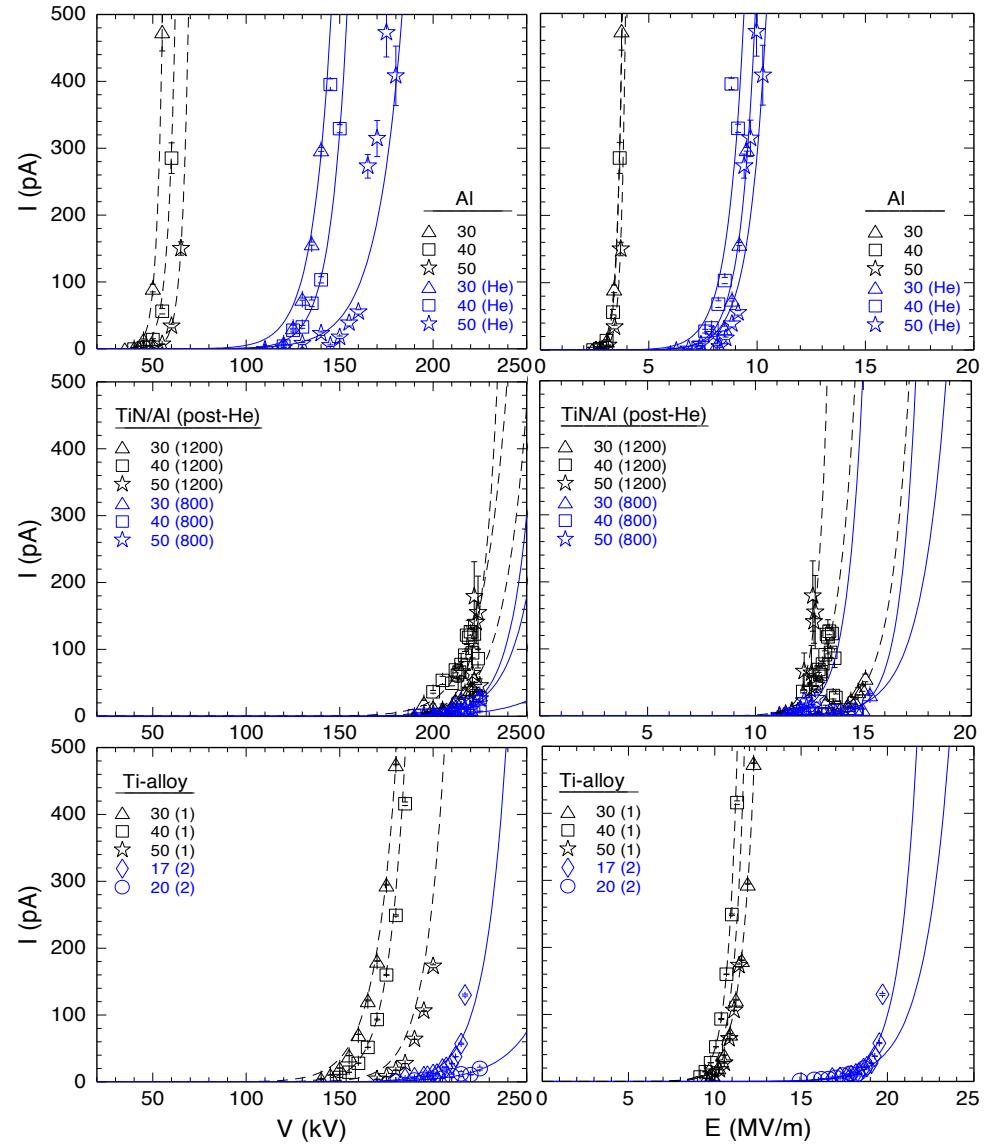
# TiN-COATED ALUMINUM



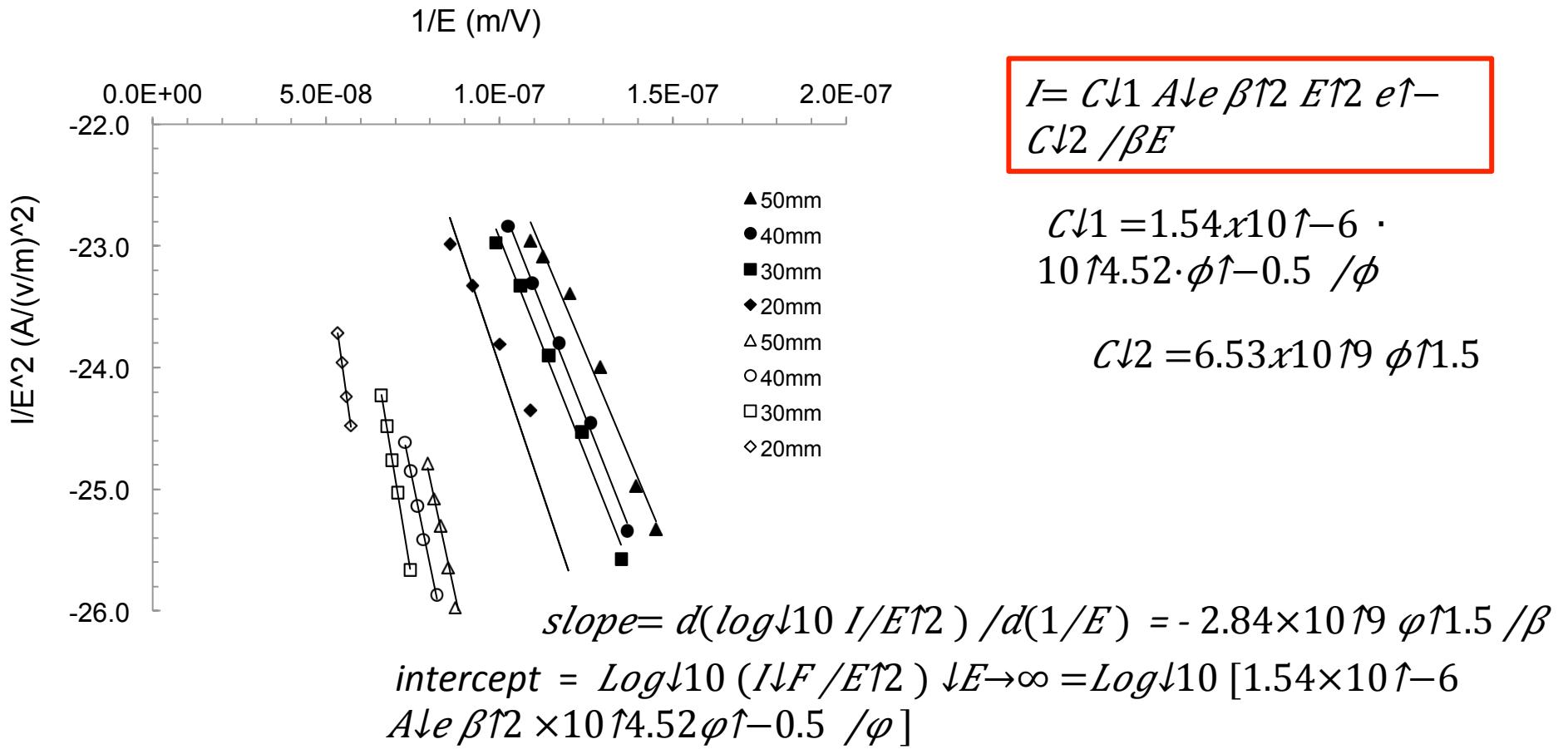
Bare aluminum:  
easily damaged



Diamond-paste  
polished Ti-alloy:  
a traditional  
“hard” electrode

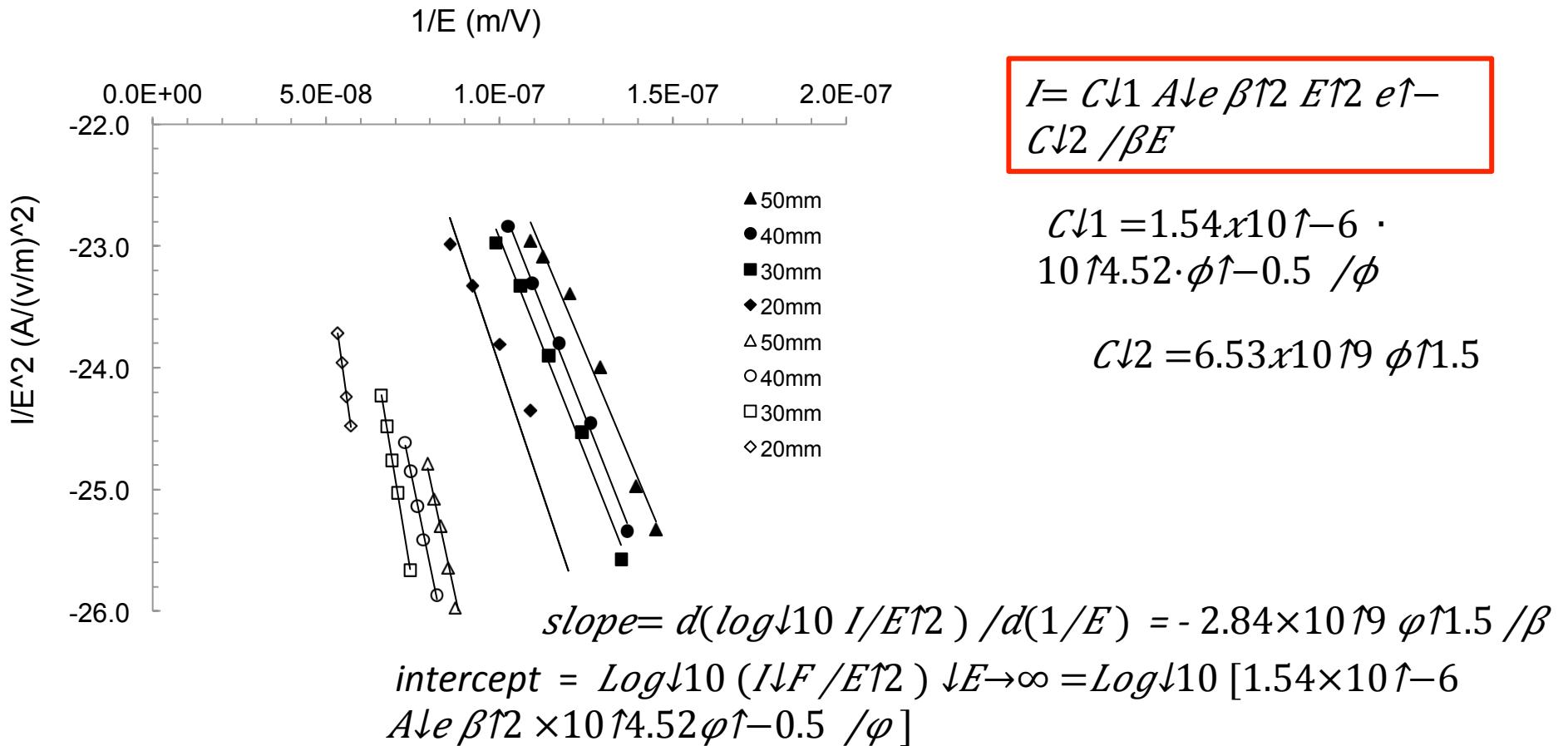


# FOWLER-NORDHEIM LINE PLOTS



- These plots tell you  $b$ , the field enhancement factor, and  $A_e$ , the field emitter area

# FOWLER-NORDHEIM LINE PLOTS



- But it's wrong to assume work function,  $F$ , is a constant
- With three variables, there are an infinite number of solutions that provide a good fit

# FOWLER-NORDHEIM LINE PLOTS

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Electrodes	$\beta$ , Pre-Gas Conditioning	$\beta$ , Post-Gas Conditioning	$A_e$ ( $m^2$ ), Pre-Gas Conditioning	$A_e$ ( $m^2$ ), Post-Gas Conditioning
EP1	413	413	1.2E-18	1.2E-18
EP2	485	362	8.5E-19	2.4E-18
EP3	501	456	5.3E-23	1.2E-22
DPP1	228	134	9.7E-19	1.1E-17
DPP2	972	299	8.4E-20	7.1E-17
DPP3	475	171	2.5E-20	1.4E-19

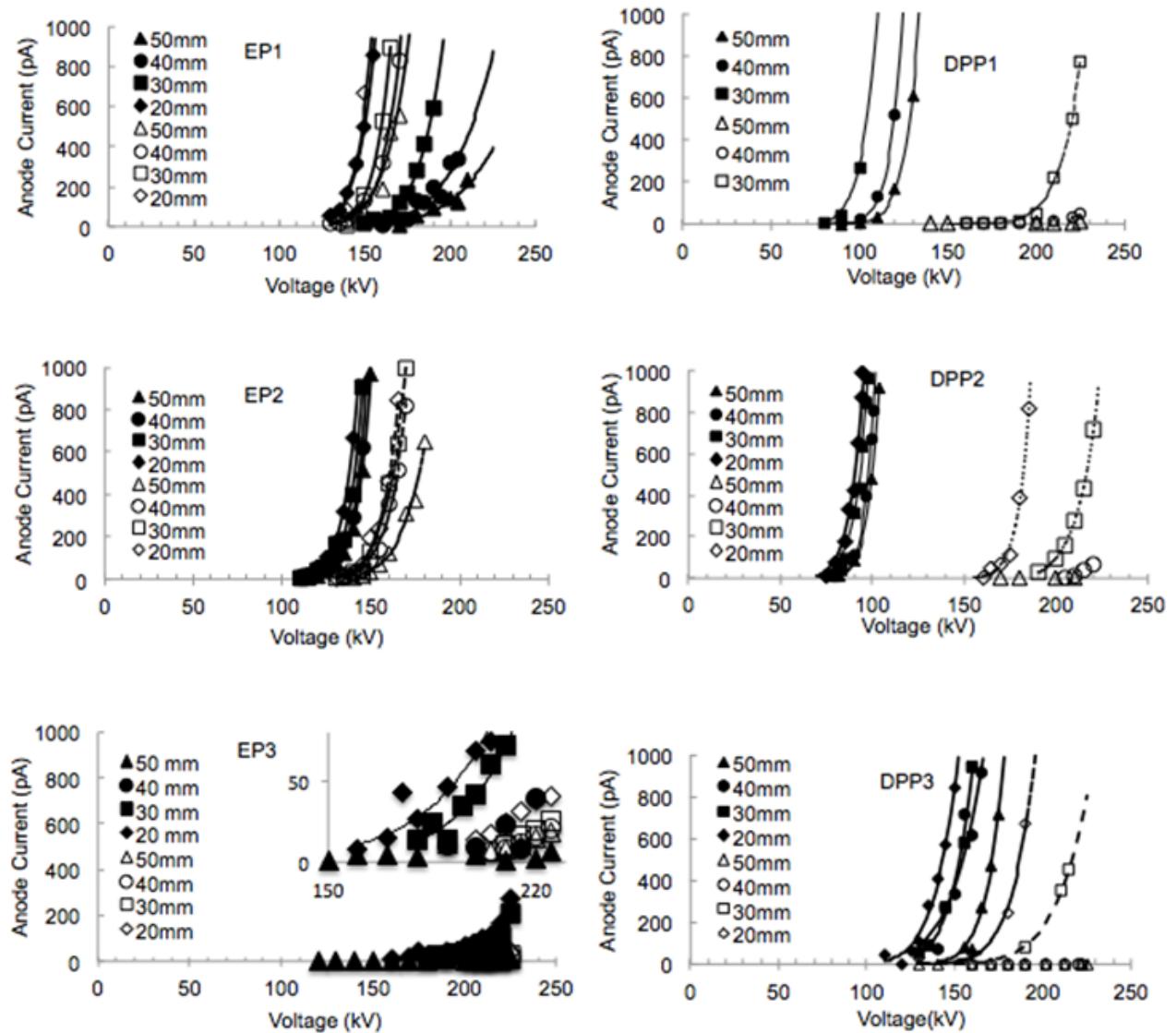
	DPP1	DPP2	DPP3	EP1	EP2	EP3
Waviness (nm)	25	30	73	312	385	76
Roughness (nm)	11	29	31	163	140	37

Why not identical here?

Identical here

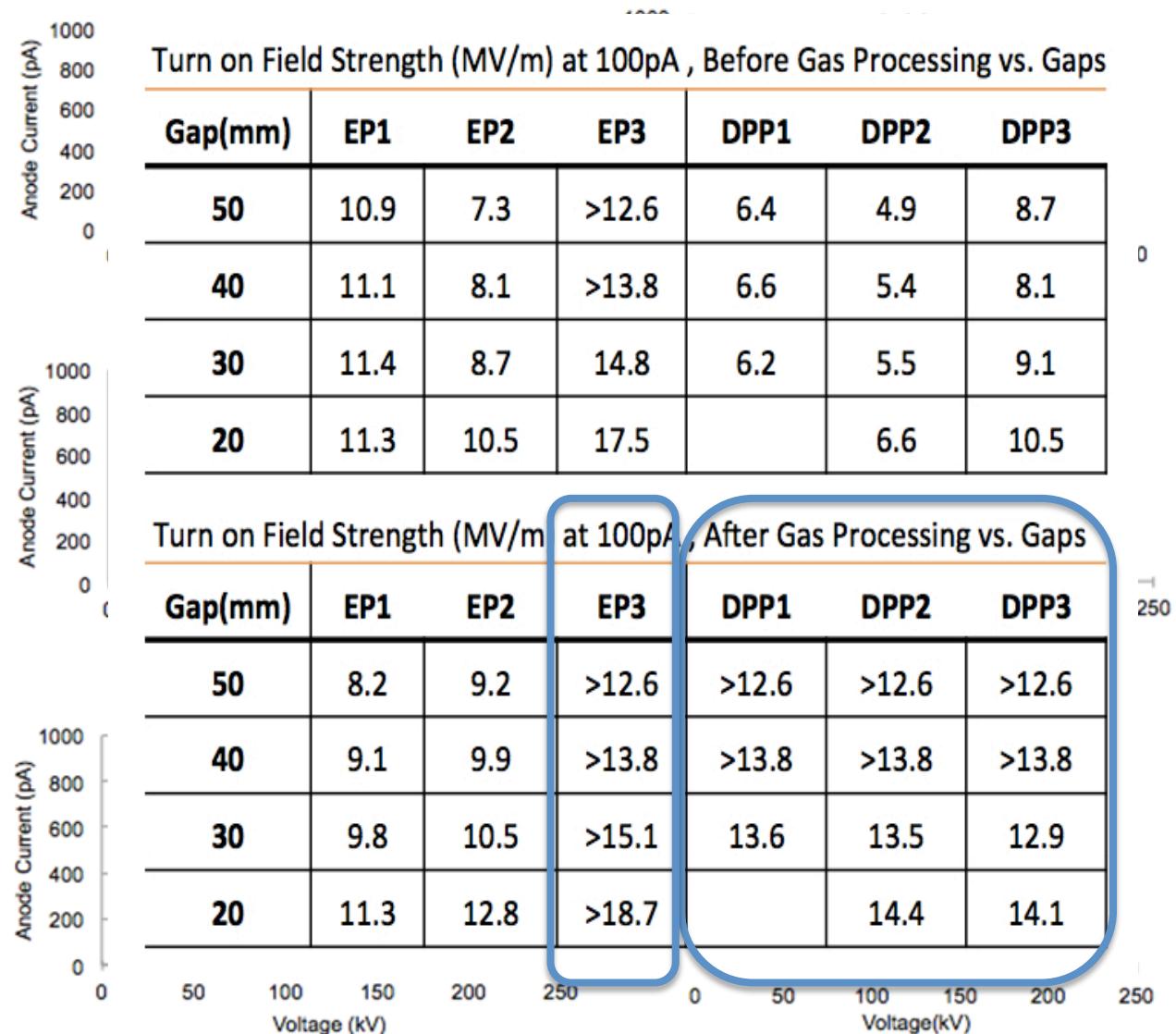
# ELECTROPOLISHED STAINLESS STEEL

- EP-d electrodes exhibited less variability
- EP-d electrodes did not respond favorably to gas conditioning
- Best electrodes were DPP-d



# ELECTROPOLED STAINLESS STEEL

- EP-d electrodes exhibited less variability
- EP-d electrodes did not respond favorably to gas conditioning
- Best electrodes were DPP-d



# BARREL POLISHING OF STAINLESS STEEL

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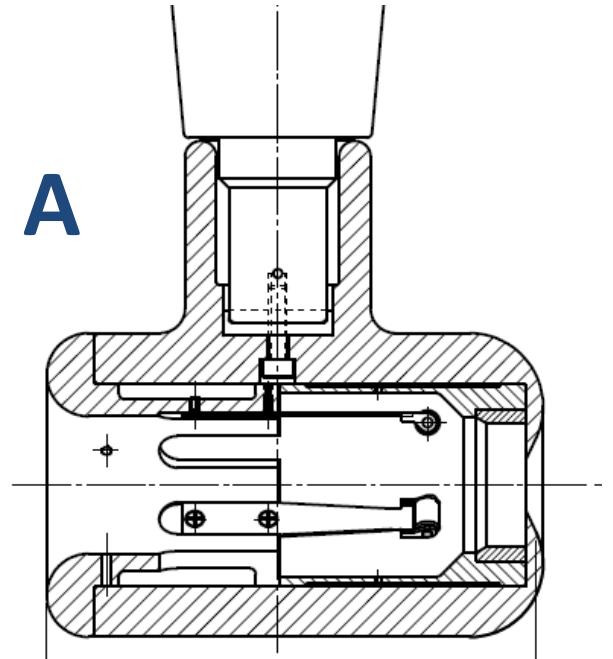
# BARREL POLISHING OF STAINLESS STEEL

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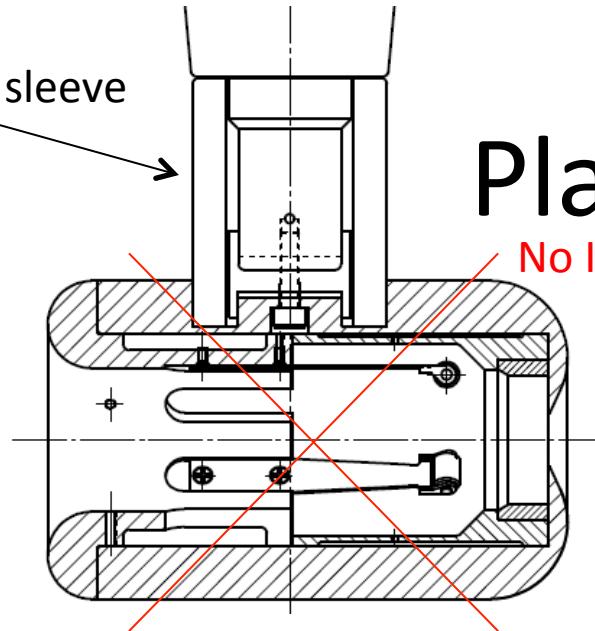
On our to-do list for testing

**Plan A**



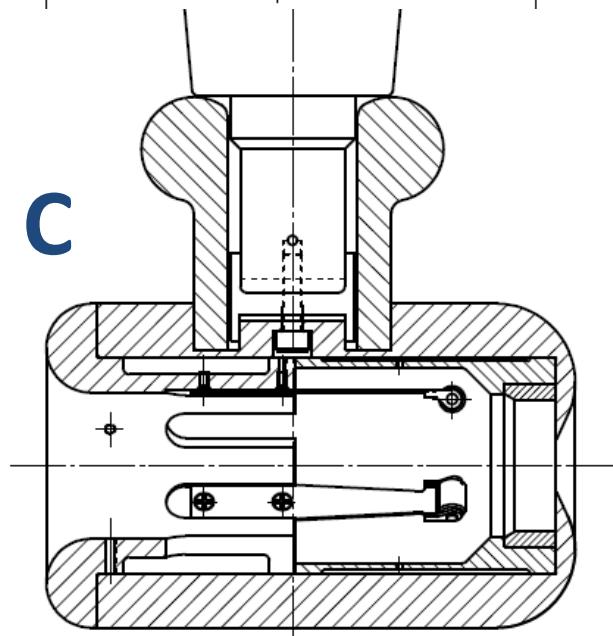
Insulator sleeve

**Plan B**

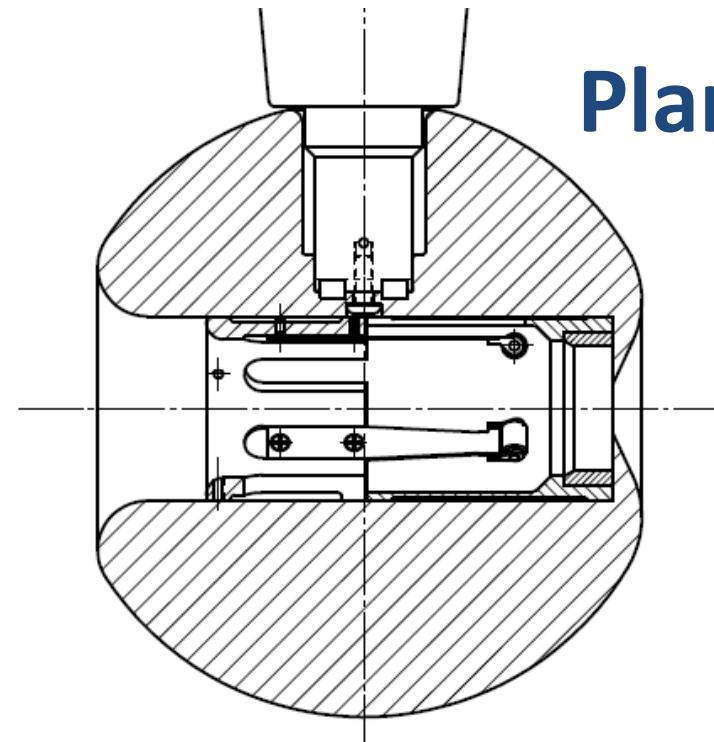


No Improvement

**Plan C**



**Plan D**

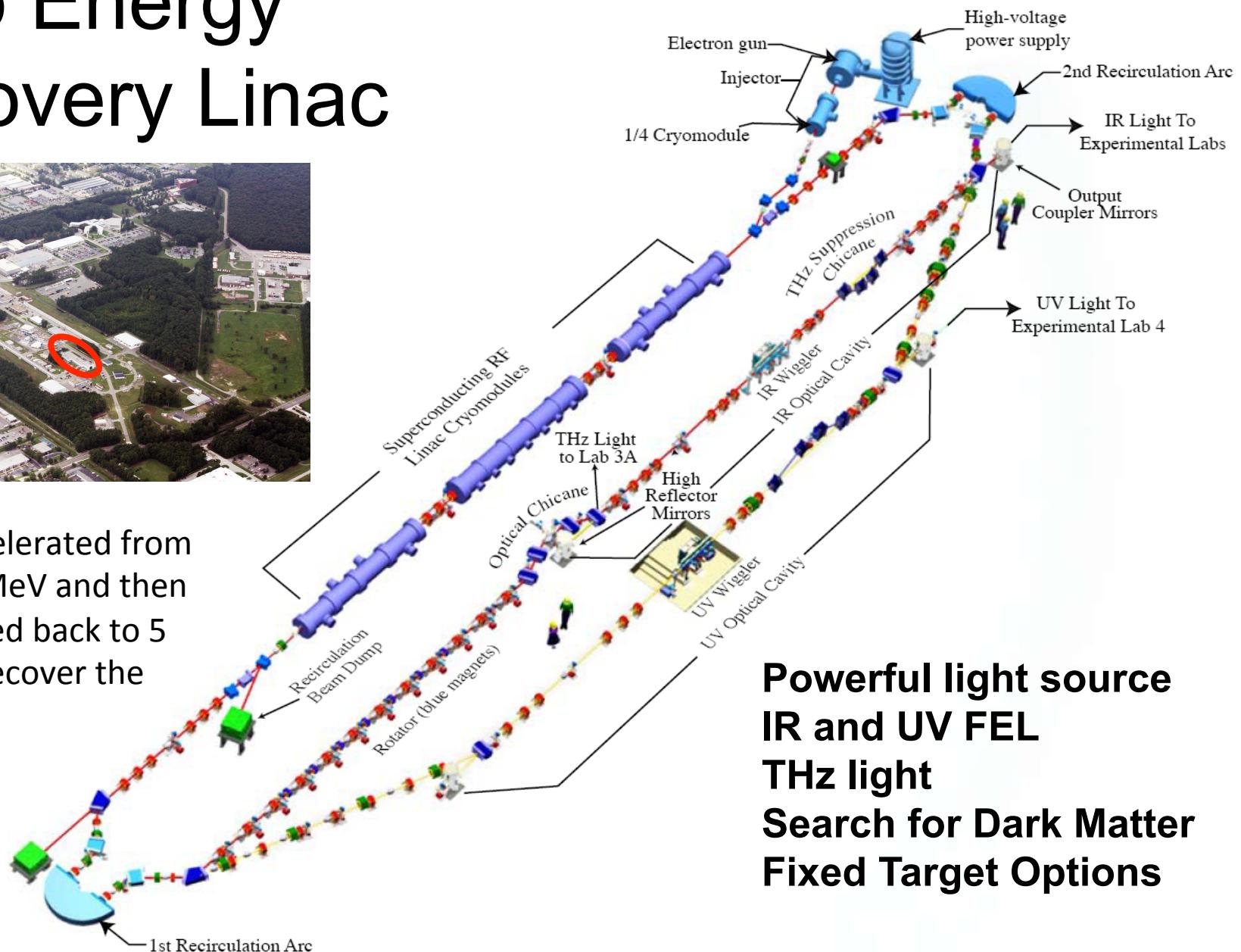


Screening electrode, or “shed”

# JLab Energy Recovery Linac



Beam accelerated from 5 to 100 MeV and then decelerated back to 5 MeV, to recover the energy

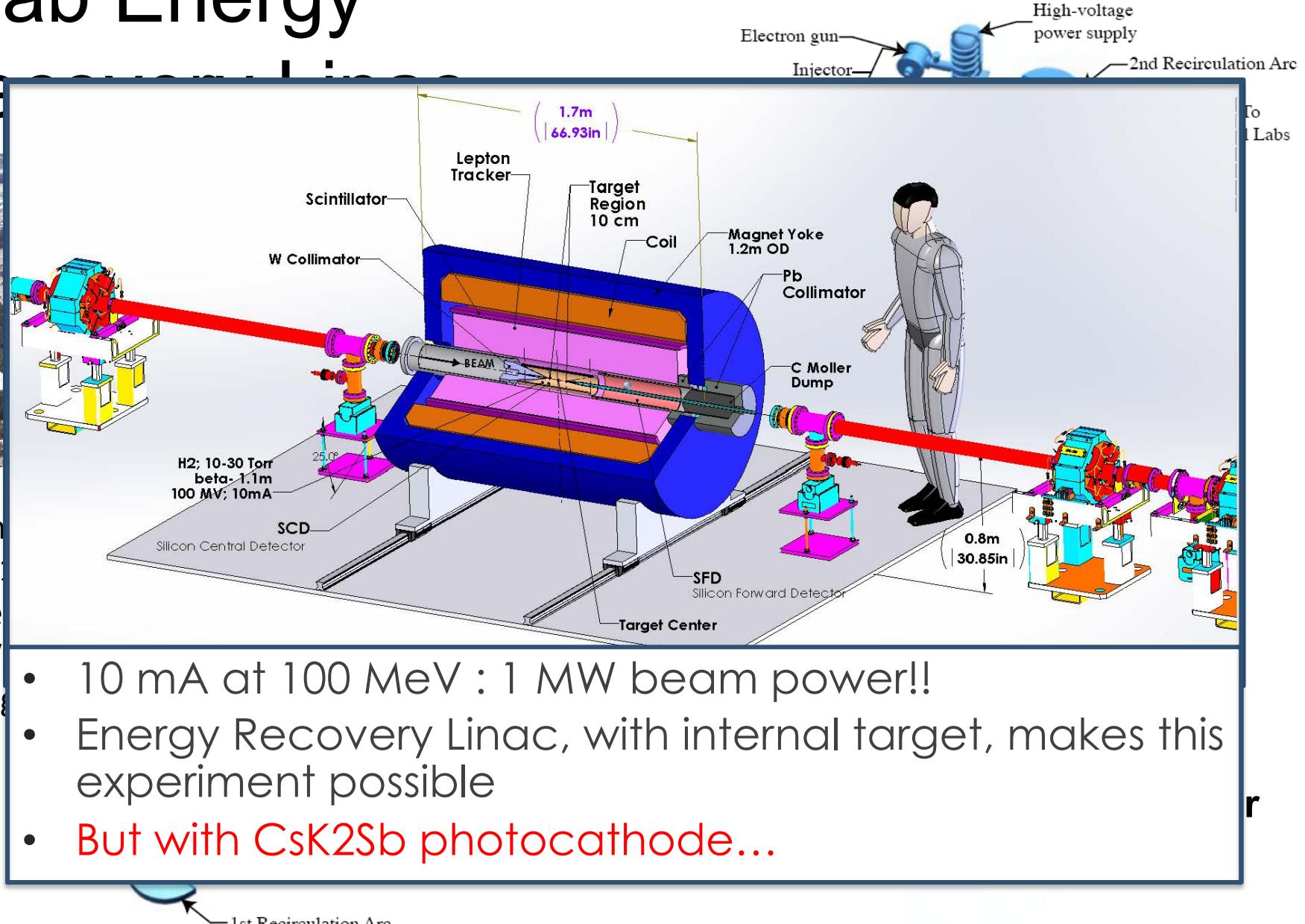


**Powerful light source  
IR and UV FEL  
THz light  
Search for Dark Matter  
Fixed Target Options**

# JLab Energy Recovery Linac

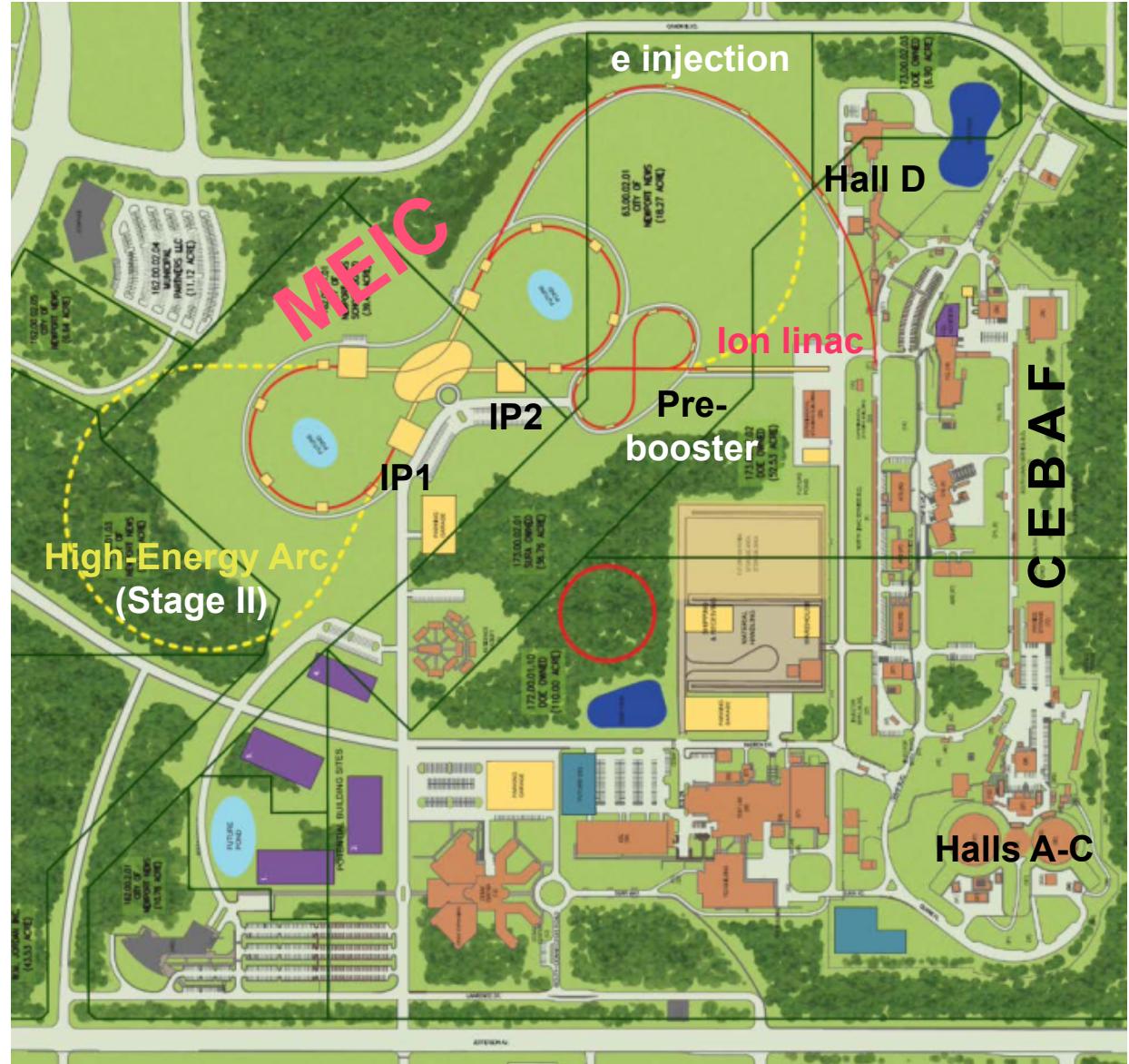


Beam  
5 to  
dece  
MeV  
energ

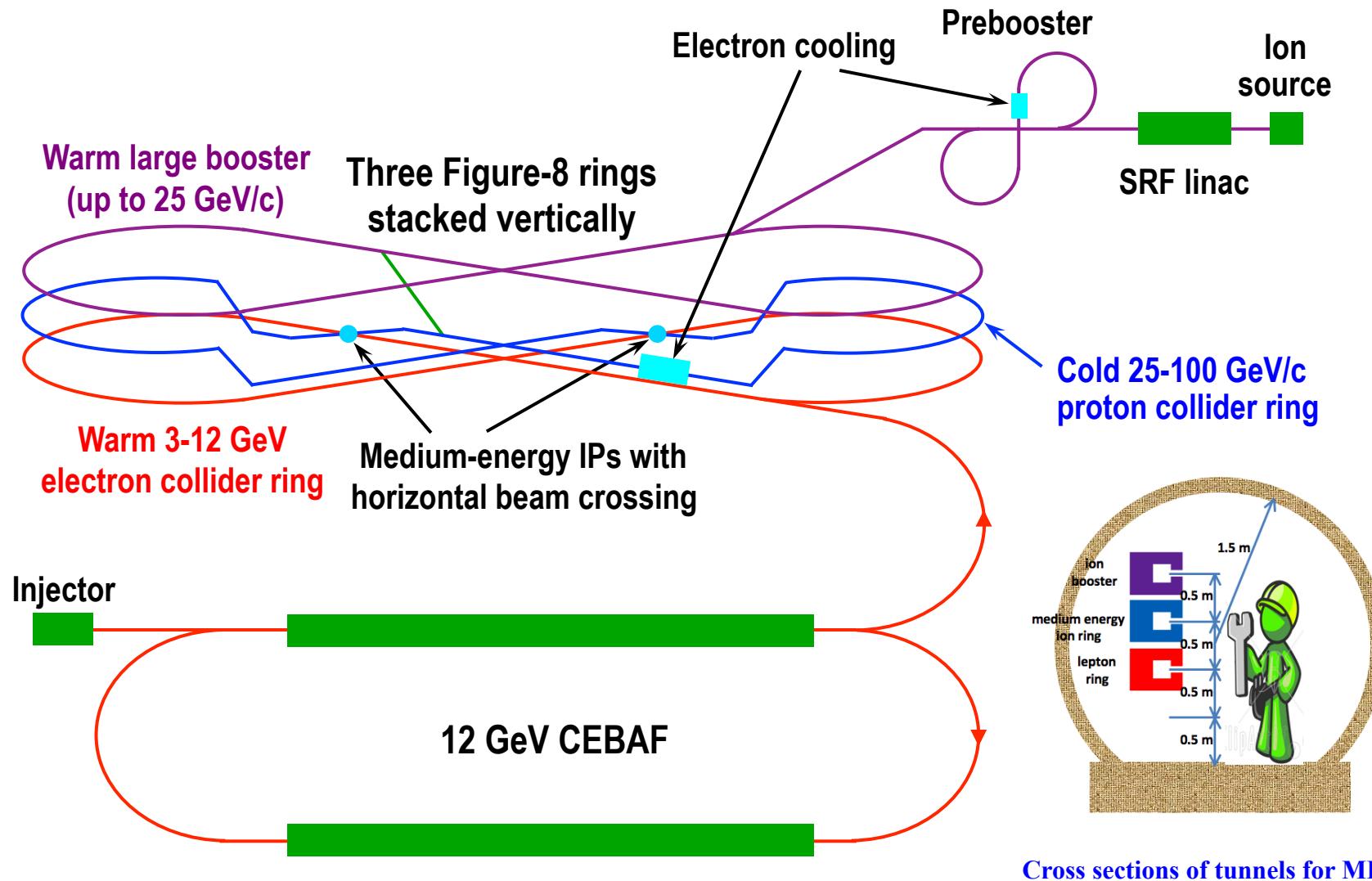


# Electron Ion Collider at JLab

- Stage I MEIC
  - CEBAF as full-energy  $e^-/e^+$  injector
  - 3 to 12 GeV  $e^-/e^+$
  - 25 to 100 GeV protons
  - 12 to 40 GeV/u ions
- Stage II EIC
  - up to 20 GeV  $e^-/e^+$
  - up to 250 GeV protons
  - up to 100 GeV/u ions
- Two independent but complementary detectors



# MEIC Layout



# Jefferson Lab

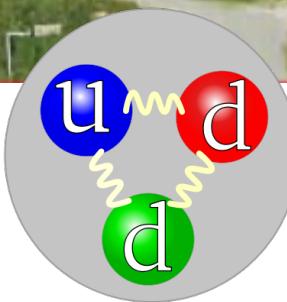
Thomas Jefferson National Accelerator Facility  
*Exploring the Nature of Matter*



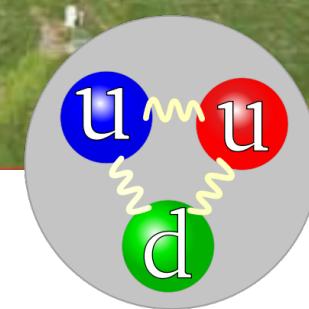
Jefferson Lab accelerator site



Electron

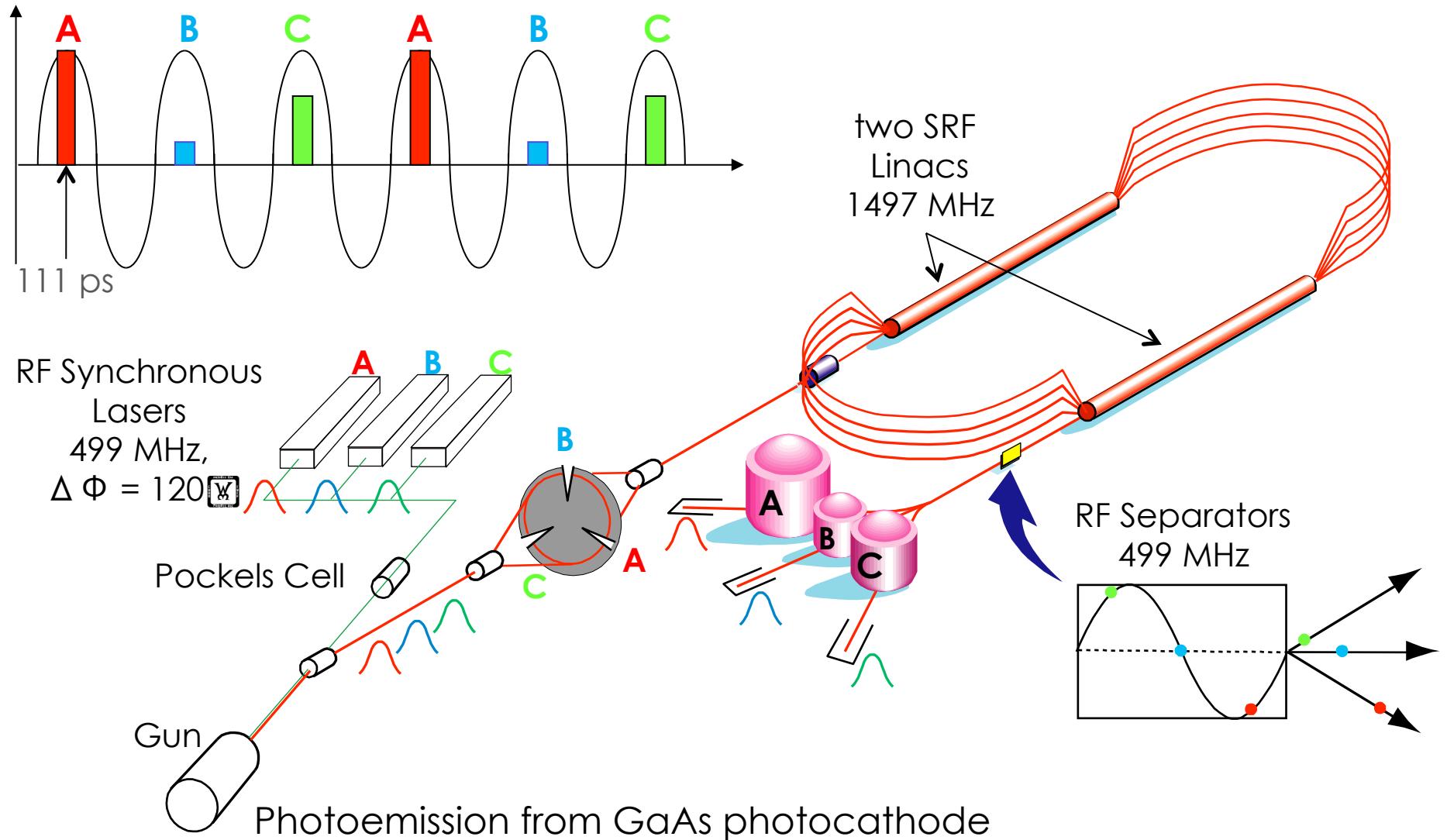


Neutron

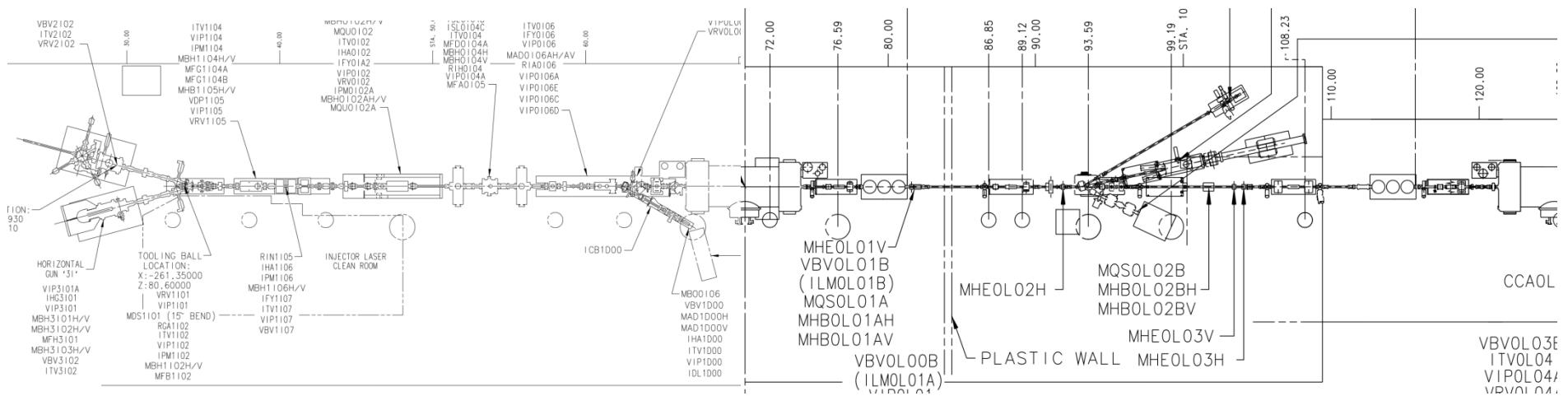


Proton

# Continuous Electron Beam Accelerator Facility

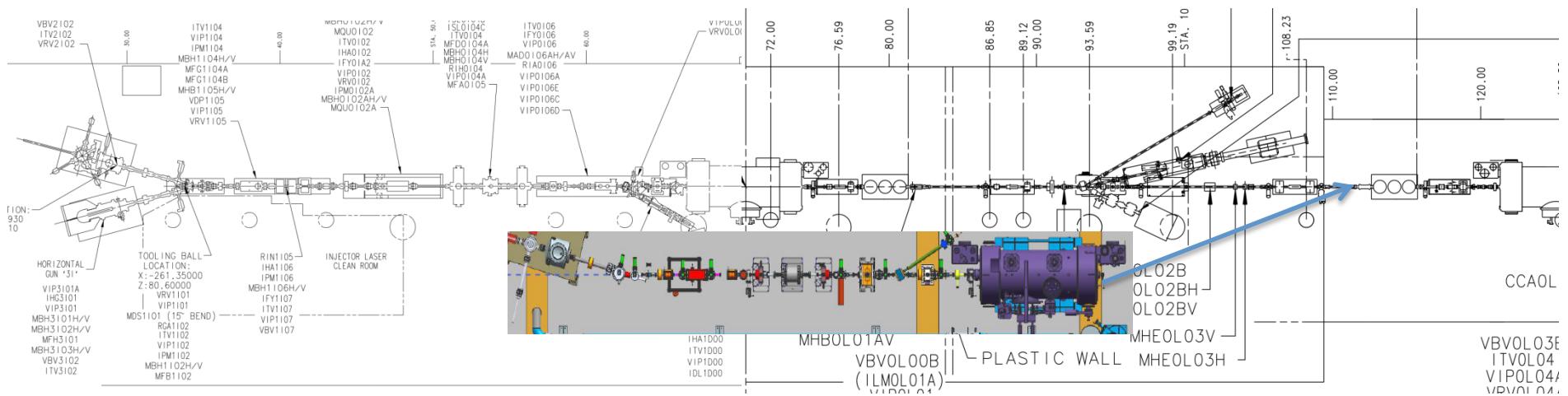


# Preparing for the next generation Parity-Violation Experiment



Proposed by Joe Grames

# Preparing for the next generation Parity-Violation Experiment



- 1) deliver 100% long polarization to two halls simultaneously - each gun/ beamline has spin manipulators
- 2) parity violation experiments can monitor helicity correlated beam properties directly from gun. No other superimposed beams from gun to merger point
- 3) apertures at injector are good for non-parity users, they keep them. Apertures are bad for parity Users, the new line could eliminate them, hopefully even the chopper
- 4) Parity violation experiments get a laser "clean-up polarizer" to provide near perfect circular polarization, which helps reduce helicity correlated beam asymmetries

Proposed by Joe Grames